# **Companion PMIC for Smartphone and Tablet**

### **General Description**

The MAX77829 is a high-performance companion PMIC for latest 3G/4G smartphones and tablets. The PMIC includes a single-input 2.0A switched-mode charger with reverse-boost capability and adapter input protection up to 22V (DC) for one-cell Lithium-lon (Li+) battery, a safeout LDO, and WLED backlight driver supporting up to 25mA/string, 35V output voltage. It also features a dual-channel 1.5A (combined, 750mA/CH) Flash LED driver (with Torch Mode included).

The typical 4MHz switched-mode battery charger with two integrated switches, providing the smallest L/C size, lowest heat and fastest programmable battery-charging current, is ideally suited for portable devices such as headsets and ultra-portable media players. The charger features single input, which works for adapter/USB type inputs. All the MAX77829 blocks connecting to the adapter/USB pin are protected from input overvoltage events. The DC pin is rated to 22V absolute maximum. The USB-OTG output provides true-load disconnect and is protected by an adjustable output current limit (default 900mA, other current limit is also available with different factory setting up to 900mA).

The battery charger drives an external p-channel MOSFET as power-path switch, and its I<sup>2</sup>C-programmable settings can accommodate a wide range of battery sizes and system loads. When configured in reverse boost mode, the MAX77829 requires no additional inductor to power USB OTG accessories and/or provide illumination to the Flash LED.

The switching charger implements a special CC, CV, and die temperature regulation algorithm; the patented MaxFlash prevents overloading a weak battery, further extending battery life.

The MAX77829 features an  $I^2C$  2.0-compatible serial interface consisting of a bidirectional serial data line (SDA) and a serial clock line (SCL).

### **Benefits and Features**

- Highly Integrated Solution
  - · Single Input Switched Mode Charger
  - Camera Flash and Torch LED Driver, Dual-Channel 750mA/ch
  - Two-String White LED Backlight Driver, 25mA/ch, 35V OVP
  - · One Safeout LDO
- Single High Efficient Switched Mode Charger
  - Supporting Up to 2.0A Charging Current Capability
  - Input-Voltage-Based Automatic Input Current Limit (AICL) Power Management
  - System Voltage Regulator/Battery Charger with External Power Path
  - · Various Charging Protection Features
- Single Input Accommodating Standard USB and High Input Voltage Adaptor
  - · 22V Absolute Maximum Input Voltage Rating,
  - up to +9.4V Maximum Operating Input Voltage
- USB OTG Capability
  - Reverse Boost Support, Up to 900mA at +5V
  - Programmable Reverse Boost Output Voltage (Up to 5.8V)
- Flexible Programmability
  - I<sup>2</sup>C 2.0 Serial Interface
- Compact Package
  - 3.64mm x 3.24mm WLP, 8 x 7 Array, 56-Bumps, 0.4mm Pitch

#### **Applications**

- Smartphone and Tablets
- Other Li-Ion Battery Power Handheld Devices

Ordering Information appears at end of data sheet.



# **Absolute Maximum Ratings**

DC, BYP to GND	0.3V to +22V
LX, BST to GND	0.3V to +12V
CS, SYSS, SYS, AVL, PVL, FET_DRV,	
MBATT, IN_FLED, CHGIND to GND	0.3V to +6V
MBATSNSP, MBATSNSN, MBATDET,	
THM to GND	0.3V to +6V
INOK to GND	0.3V to $(V_{SYS} + 0.3V)$
LX, CHGPG Continuous Current	2A <sub>RMS</sub>
DC, BYP Continuous Current	2A <sub>RMS</sub>
FLED to GND	0.3V to $(V_{BYP} + 0.3V)$
TORCHEN, FLASHEN to GND	
FLED1, FLED2 Current	0.8A <sub>RMS</sub>
SAFEOUT to GND	0.3V to $(V_{DC} + 0.3V)$
SAFEOUT Continuous Current	100mA
WLEDOUT, WLED1, WLED2 to GND	0.3V to +36V

WLEDGND, WLEDPGND to GND	
WLEDPWM to GND	
WLEDLX Continuous Current	1.2A <sub>RMS</sub>
VIO to GND	0.3V to +6V
SDA, SCL to GND	$-0.3V$ to $(V_{VIO} + 0.3V)$
MRST, RESET, INT to GND0.3	$3V \text{ to } (V_{SYS A} + 0.3V)$
TEST_, VCCTEST, SYS_ to GND	0.3V to +6V
GND_ to GND	0.3V to +0.3V
Continuous Power Dissipation (T <sub>A</sub> = +70°	°C)
WLP (derate 25mW/°C above 70°C)	2000mW
Operating Temperature	40°C to +85°C
Junction Temperature	
Storage Temperature Range	65°C to +150°C
Soldering Temperature (reflow)	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **Package Thermal Characteristics (Note 1)**

WLP

Junction-to-Ambient Thermal Resistance ( $\theta_{JA}$ ) ........40°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

### **Electrical Characteristics**

 $(V_{DC}$  = 5V,  $C_{BYP}$  = 2.2 $\mu$ F,  $C_{PVL}$  =  $C_{AVL}$  = 10 $\mu$ F,  $C_{SYS}$  = 10 $\mu$ F,  $C_{MBAT}$  = 4.7 $\mu$ F,  $T_A$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $T_A$  = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DC INPUT						
DC Operating Voltage Range			3.5		V <sub>OVLO</sub> (min)	V
DC Startup Voltage Range			4.0		V <sub>OVLO</sub>	V
DC Undervoltage Lockout	V <sub>UVLO</sub>	DC rising, 500mV hysteresis	3.6	3.8	4.0	V
DC Overvoltage Lockout	V <sub>OVLO</sub>	DC rising, 3% hysteresis, contact factory for alternate thresholds (5.9V, 7.5V, 9.7V)	6.3	6.5	6.7	V
DC_V Threshold	V <sub>DC_V</sub>	DC rising, 200mV hysteresis	5.7	5.8	5.95	V
DC Overvoltage Interrupt Delay				16		ms
DC Insertion Debounce Time	t <sub>DBDC</sub>		100	120	150	ms
DC to SYS Shutdown Threshold		When charging stops, V <sub>DC</sub> falling, 150mV hysteresis	0	50	100	mV

 $(V_{DC} = 5V, C_{BYP} = 2.2 \mu F, C_{PVL} = C_{AVL} = 10 \mu F, C_{SYS} = 10 \mu F, C_{MBAT} = 4.7 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25 ^{\circ}C.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	COND	ITIONS	MIN	TYP	MAX	UNITS
		USB suspend, V <sub>DC</sub> = 5.5	5V			0.5	
DC Supply Current	I <sub>DC</sub>	Charger enabled, f = 4M V <sub>SYSMIN</sub> = 3.55V, QBAT			2		mA
DC Current Limit		Programmed DCILMT[5:0], minimum			0.1		
DC Current Limit	IDC_ILIM	Programmed DCILMT[5:	:0], typical		2		- A
		USB 100mA mode		90	95	100	
Input Current Limit Accurancy		USB 500mA mode		450	475	500	mA
riodularioy		Programmed to 1.5A		1350	1500	1650	]
Adaptive Input Current Limit (AICL) Voltage	V <sub>DC_AICL</sub>	DC voltage where charg programmable from 4.0\ increments (4.5V setting	/ to 4.6V in 100mV	4.410	4.5	4.635	V
Threshold		DC voltage where the ch to its minimum value (75			V <sub>DC_AICL</sub> - 0.1		V
Input Limit Switch		V <sub>DC</sub> = 5.5V, I <sub>BYP</sub> = 100r	mA		50	100	mΩ
LEAKAGE CURRENT	•	,					
BST Leakage Current		V <sub>BST</sub> = V <sub>LXCHG</sub> = 5.5V, V <sub>DC</sub> = V <sub>PGCHG</sub>	T <sub>A</sub> = +25°C		0.01	10	μA
		V <sub>SYS</sub> = 3.7V	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		0.1		μΛ
MBATT Reverse-Leakage		V <sub>MBAT</sub> = 4.2V,	T <sub>A</sub> = +25°C		0.01	10	
Current		V <sub>DC</sub> = 0V	T <sub>A</sub> = -40°C to +85°C		0.1		– μA
<b>BUCK CONVERTER OPE</b>	RATION						
Switching Frequency		V <sub>MBAT</sub> = 3.7V			4		MHz
Max Duty Cycle						99.5	%
Minimum On-Time					35		ns
Maximum On-Time					10		μs
Minimum Off-Time					35		ns
Soft-Start Time					1.5		ms
High-Side Resistance		I <sub>LX</sub> = 100mA, V <sub>DC</sub> = 5.5	V		130	250	mΩ
Low-Side Resistance		I <sub>LX</sub> = 100mA, V <sub>DC</sub> = 5.5	V		150	220	mΩ
			Minimum		75		
Thermal Regulation Temperature		Programmable-2 bits, see the REGTEMP[1:0]	Maximum		120		°C
Temperature		See the INLOTE WIF [1.0]	Step size		15		1
BATTERY CHARGER							-
Pre-Charge Lower Threshold	V <sub>PQLTH</sub>	V <sub>MBATT</sub> rising, 125mV hysteresis, contact the factory for alternative selection for 2.1V, 2.2V, 2.3V, 2.4V, 2.5V, 2.6V, 2.7V, 2.8V			2.1		V
Dead-Battery Charge Current	I <sub>PQLTH</sub>	0V ≤ V <sub>MBAT</sub> ≤ V <sub>PQLTH</sub>			40		mA

 $(V_{DC} = 5V, C_{BYP} = 2.2 \mu F, C_{PVL} = C_{AVL} = 10 \mu F, C_{SYS} = 10 \mu F, C_{MBAT} = 4.7 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25 ^{\circ}C.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDITION	ONS	MIN	TYP	MAX	UNITS
Precharge Upper Threshold	V <sub>PQUTH</sub>	V <sub>MBAT</sub> rising, 150mV hyste factory for alternative setting			3.4		V
Precharge Current	I <sub>PRECHG</sub>	Contact factory for alternati 200mA, 300mA, 400mA) w setting			200		mA
CONSTANT CURRENT M	IODE						
BATT Fast-Charge Current Range	I <sub>FCHG</sub>	Programmable 50mA steps, RCS = 47mΩ	Minimum Maximum		250 2000		mA
Fast-Charge Current Accuracy (Voltage Across		$R_{CS} = 47 \text{m}\Omega$ , $V_{RCS} =$	T <sub>A</sub> = +10°C to +45°C	-5		+5	- %
R <sub>CS</sub> )			JEITA Safety Region	-65	-50	-35	
CONSTANT VOLTAGE M	ODE						
Battery Regulation		Programmable with	Minimum		3.55		V
Voltage Range		MBATREG[3:0]	Maximum		4.4		V
		When the charger is	T <sub>A</sub> = +25°C	-0.5		+0.5	- %
		regulating battery voltage	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	-1		+1	,,
Battery Regulation Voltage Accuracy  VMBATT	Charger is regulating battery voltage , VMBATREG = 4.2V (MBATREG[3:0]=0b1011), VMBATREG = 4.35V	When JEITA is enabled (JEITA_EN=1) and the battery temperature is in the "COOL" Region, the battery regulation voltage will be this much lower than the value programmed by MBATREG[3:0].		150		mV	
Battery Refresh	V <sub>MBATREG</sub> = 4.35V (MBATREG[3:0]=0b1111)	(MBATREG[3:0]=0b1011),	CHGRSTRT = 0	1	3	5	- %
Threshold		the DONE state, it will restart when the battery falls this percentage below V <sub>MBATREG</sub> (MBATREG[3:0])	CHGRSTRT = 1	2	4	6	/0
Battery Overvoltage Protection	V <sub>MBAT</sub> _	V <sub>MBATREG</sub> = 4.2V (MBATR V <sub>MBATREG</sub> = 4.35V (MBAT VMBATT threshold over req hysteresis 2.2% (V <sub>BAT</sub> falling	REG[3:0]=0b1111) gulation voltage,	102	104	106	%

 $(V_{DC} = 5V, C_{BYP} = 2.2 \mu F, C_{PVL} = C_{AVL} = 10 \mu F, C_{SYS} = 10 \mu F, C_{MBAT} = 4.7 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25 ^{\circ}C.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDITION	ONS	MIN	TYP	MAX	UNITS
Charge Current		I <sup>2</sup> C programmable, see	Minimum		50		
Termination Threshold	I <sub>DONE</sub>	I <sub>TOPOFF</sub> [2:0]. I <sub>DONE</sub> current independent of	Maximum		400		mA
Range		JEITA functionality	Step size		50		
Charge Current Termination Deglitch Time		2mV overdrive			16		ms
Charge Current		I <sub>DONE</sub> = 200mA		180		224	
Termination Accuracy		I <sub>DONE</sub> = 50mA		35		70	- mA
VICHG							
		.,	I <sub>OUT</sub> = 50mA		70.5		
VICHG Output Voltage		V <sub>ICHG_GAIN</sub> = 0, 1.41mV/mA	I <sub>OUT</sub> = 1000mA	1260	1410	1540	mV
		1.411117/110	I <sub>OUT</sub> = 1500mA		2150		
CHARGER TIMER							
Dead-Battery and	toppour	USB 500mA mode (t <sub>PREC</sub>	HG_500)		14	16	min
Precharge Time	tPRECHG	USB 100mA mode (t <sub>PREC</sub>	HG_100)		39	45	111111
Fast-Charge Time Range		I <sup>2</sup> C programmable, refer	Minimum		4		
	t <sub>FCHG</sub>	to FCHGTIME[2:0] for detailed values	Maximum		16		hour
Fast-Charge Timer Accuracy		Default 5 hours setting			5	6	hour
		I <sup>2</sup> C programmable (See the T <sub>OPOFFT</sub> [2:0])	Minimum		0		min
Top-Off Time	t <sub>TOPOFF</sub>		Maximum		60		
			Step size		10		
Top-Off Timer Accuracy		Default 30 minute setting			20		%
Timer Extend Current Threshold		Percentage of fast-charge of the timer clock operates at JEITA is enabled)			50		%
REVERSE BOOST							
BYP Reverse Boost		Programmable with	Minimum		3.0		
Voltage Adjustment		RBOUT[3:0], 2.6V < V <sub>SYS</sub>	Maximum		5.8		V
Range		< V <sub>BYP</sub> - 0.5V	Step size		0.025		
Reverse Boost Quiescent Current		Switching			2.1		mA
Reverse Boost Voltage Accuracy		5.1V setting, 0mA < I <sub>LOAD</sub> < 500mA		4.94	5.1	5.36	V
Reverse Boost Converter Maximum Output Current		V <sub>SYS</sub> = 3.7V(minimum requirements)		1500			mA

 $(V_{DC} = 5V, C_{BYP} = 2.2 \mu F, C_{PVL} = C_{AVL} = 10 \mu F, C_{SYS} = 10 \mu F, C_{MBAT} = 4.7 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25 ^{\circ}C.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDIT	IONS	MIN	TYP	MAX	UNITS
Reverse Boost Output		Discontinuous inductor cu	rrent (i.e. skip mode)		±50		mV
Voltage Ripple		V <sub>BAT</sub> = 3.6V, V <sub>BYP</sub> = 5.5V	, I <sub>BYP</sub> = 100mA		±50		mV
DC Output Capacitor		Device included	Device included			22	μF
Maximum DC Output Current		V <sub>SYS</sub> = 3.7V		900			mA
DC Output Current Limit	OTGILIM			1000		1970	mA
OTGILIM Interrupt Debounce					30		ms
Reverse Boost Output		When DC output current	Retry on-time		0.5		ma
Voltage Ripple		hits OTGILIM	Retry off-time		330		ms
Inductor Peak Current Limit			·		3.9	4.40	А
BYP_UVLO		Falling		4.30	4.35	4.45	V
BYP_UVLO Hysteresis					150		mV
BAT-SYS-FET DRIVER				•			
FET_DRV Output High		I <sub>SOURCE</sub> = -1mA		V <sub>PVL</sub> - 0.2			V
FET_DRV Output Low		I <sub>SINK</sub> = 1mA				0.2	V
Minimum V <sub>SYS</sub>		Minimum			3.0		
Regulation Voltage	V <sub>SYSMIN</sub>	Programmable with V <sub>SYSREG</sub> [2:0]	Maximum		3.6		V
Range		*515REG[2.0]	Step size		0.1		
MBATT to SYS FET		Turn-on threshold (V <sub>MBAT</sub>	<sub>T</sub> rising)		$V_{PQUTH}$		V
Turn-On Threshold		Turn-off threshold (V <sub>MBAT</sub>	T falling)		V <sub>PQUTH</sub> - 0.15		V
Supplement Mode		Entering supplement mode	e when V <sub>SYS</sub> < V <sub>BAT</sub>	25	40	50	mV
Threshold Level		Exiting supplement mode		10			mV
BATTERY OVERCURRE	NT THRESH	OLD					
Battery Overcurrent Threshold Alarm		$R_{BATRSNS} = 5m\Omega$ , BAT2SOC[1:0] = 4.0A setting, overcurrent from BAT to SYS sensed through the $5m\Omega$ resistor, it does not shut off external FET, but provides an overcurrent interrupt through BAT_I to the processor		16	20	24	mV
Battery Overcurrent Debounce Time		4ms setting (programmable	from 4ms to 10ms)	3.8	4.0	4.2	ms

 $(V_{DC} = 5V, C_{BYP} = 2.2 \mu F, C_{PVL} = C_{AVL} = 10 \mu F, C_{SYS} = 10 \mu F, C_{MBAT} = 4.7 \mu F, T_A = -40 ^{\circ}C \text{ to } +85 ^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25 ^{\circ}C.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDITI	ONS	MIN	TYP	MAX	UNITS
BATTERY DETECTION	'	-					
Low-Cost Battery		V <sub>INI2C</sub> = 1.8V, V <sub>MBATDET</sub> rising, 60mV hysteresis		1.063	1.1	1.136	V
Presence Detection Voltage				59.1	61.1	63.1	% V <sub>INI2C</sub>
High-Cost Battery		V <sub>INI2C</sub> = 1.8V, V <sub>MBATDET</sub> I hysteresis	rising, 20mV	1.454	1.5	1.536	V
Presence Detection Voltage		Turn off threshold (V <sub>MBAT1</sub>	r falling)	80.8	83.3	85.3	% V <sub>INI2C</sub>
Battery Disconnect		V <sub>INI2C</sub> = 1.8V, V <sub>MBATDET</sub> I hysteresis	rising, 60Mv	1.621	1.65	1.676	V
Detection Voltage		Turn-off threshold (V <sub>MBAT</sub>	falling)	90.1	91.6	93.1	% V <sub>INI2C</sub>
Battery Detection			Minimum		0		
Debounce Timer (BAT_		Programmable with TDEB_BATREM[4:0]	Maximum		976		μs
REMOVED)		TOED_DATREM[4.0]	Step Size		30.5		
Strong Pullup Resistor		STRONGPUENB=0		2.4	4.7	9.4	kΩ
MBATDET Leakage		$V_{\text{INI2C}}$ = 5.5V, $V_{\overline{\text{MBATDET}}}$ = 0V $T_{\text{A}}$ = +25°C $V_{\text{INI2C}}$ = 5.5V, $V_{\overline{\text{MBATDET}}}$ = 0V $T_{\text{A}}$ = +85°C		-1	0.01	+1	
Current					0.1		μA
THERMISTOR MONITOR	(Threshold	s are calculated for R25 =	100k $\Omega$ and $\beta$ = 4050K)				•
THM Threshold, Cold, No Charge (-7°C)	T1	V <sub>THM</sub> /V <sub>AVL</sub> rising, 2% hystemperature falling)	teresis (thermistor	75.4	77.9	80.4	%
THM Cool Threshold (10°C)	T2	V <sub>THM</sub> /V <sub>AVL</sub> rising, 2% hysi temperature falling), Disab register		61.5	64	66.5	%
THM Warm Threshold (45°C)	Т3	V <sub>THM</sub> /V <sub>AVL</sub> falling, 2% hysteresis (thermistor temperature rising) , Disabled through JEITA_EN register		30.47	32.97	35.47	%
THM Threshold, Hot, No Charge (56°C)	T4	V <sub>THM</sub> /V <sub>AVL</sub> falling, 2% hys temperature rising)	teresis (thermistor	23.1	25.6	28.1	%
TUM Lookoga Coman'		\\ _\\\\\\\	T <sub>A</sub> = +25°C	-0.2	+0.01	+0.2	
THM Leakage Current		$V_{THM} = V_{AVL}$ or $0V$	T <sub>A</sub> = +85°C		0.1		μA

 $(V_{DC} = 5V, C_{BYP} = 2.2\mu\text{F}, C_{PVL} = C_{AVL} = 10\mu\text{F}, C_{SYS} = 10\mu\text{F}, C_{MBAT} = 4.7\mu\text{F}, T_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}, \text{ unless otherwise noted. Typical values are at } T_{A} = +25^{\circ}\text{C}.) \text{ (Note 2)}$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
PVL/AVL OUTPUTS				,			•
Dropout Voltage	V <sub>DO</sub>	V <sub>SYS</sub> = 3.6V, I <sub>AVL</sub> =	V <sub>DC</sub> = 4.5V		50		mV
Dropout voltage	, DO	30mA, $V_{DO} = V_{BYP} - V_{AVL}$	V <sub>DC</sub> = 0V		18		IIIV
Current Limit					400		mA
Maximum Output Current	I <sub>AVLMAX</sub>			100			mA
AVL/PVL POK Output Threshold		Threshold where internal peturns on	ower rails to charger		2.7		V
AVL/PVL Regulated Output		I <sub>AVL</sub> = 0V to I <sub>PVLMAX</sub> , V <sub>DC</sub> = 5.5V		4.75	5.00	5.25	V
INOK	•						
Output Low Voltage		I <sub>SINK</sub> = 1mA	SINK = 1mA			0.4	V
Output High Lookage		V <sub>SYS</sub> = 5.5V	T <sub>A</sub> = +25°C	-1	0	+1	μA
Output High Leakage	ut High Leakage	VSYS = 3.3V	T <sub>A</sub> = +85°C		0.1		μΑ
CHGIND							
Output Low Voltage		I <sub>SINK</sub> = 10mA				0.4	V
Output High Leakage		V <sub>SYS</sub> = 5.5V	T <sub>A</sub> = +25°C	-1	0	+1	μA
Output High Leakage		VSYS - 5.5V	T <sub>A</sub> = +85°C		0.1		μΑ
THERMAL SHUTDOWN							
Thermal Shutdown Temperature					160		°C
Thermal Shutdown Hysteresis					15		°C
BYP to IN_FLED SWITCH	ĺ	-					
IN_FLED Switch Resistance		V <sub>BYP</sub> = 5.0V, loading = 150	V <sub>BYP</sub> = 5.0V, loading = 150mA		160	320	mΩ

### **LED Flash Driver EC Characteristics**

 $(V_{SYS} = 3.7V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS MIN TYP M		MAX	UNITS	
FLASH DC-DC STEP-UP	CONVERTE	R (Shared with switch mode charger)				
Adaptive Control Range	V <sub>IN_FLED</sub>	Adaptive controlled	3.3		5.5	V
Adaptive Output Voltage Regulation Threshold		V <sub>IN_FLED-VFLED_</sub> , I <sub>FLED_</sub> = 750mA		250		mV
Adaptive Regulation Step Size		Smallest step that the output will regulate to		25		mV

# **LED Flash Driver EC Characteristics (continued)**

 $(V_{SYS} = 3.7V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDI	TIONS	MIN	TYP	MAX	UNITS
FLED CURRENT REGULA	ATOR						
IN_FLED Supply Current					1.1		mA
Current Setting for FLED_			Current range in Flash mode in 23.436mA/step, powered from IN_FLED (FLED1NUM=0)			750	mA
(i.e., FLED1 or FLED2)		Current range in Torch m	ode in 23.436mA/step	23.436	,	375	1
Cumment Assumes:		93mA setting; V <sub>BYP</sub> =	T <sub>A</sub> = +25°C	-2.5		+2.5	0/
Current Accuracy		5V; V <sub>FLED</sub> = 4.2V	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	-4.5		+6.5	- %
Current Regulator		750mA setting, 10% drop V <sub>BYP</sub> = 3.3V	in output current,		220	350	- mV
Dropout		750mA setting, 1% drop i	750mA setting, 1% drop in output current,		220		1 mv
Turn-Off Time			rom FLASHEN falling edge or TORCHEN alling edge or timer expire until ramping of			1.5	μs
FLED1/FLED2 Current Ramping Down		Time taken for ramping c setting to OFF setting	Fime taken for ramping current from 750mA setting to OFF setting				μs
FLED1/FLED2 Leakage		V <sub>IN FLED</sub> = 5.5V,	T <sub>A</sub> = +25°C		0.01	5	μA
in Shutdown		V <sub>FLED</sub> _ = 0V	$T_A = +85^{\circ}C$		0.1		μA
PROTECTION CIRCUITS							
Flash Duration Timer		In 62.5ms steps		62.5		1000	ms
Flash Duration Timer Accuracy				-10		+10	%
Flash Safety Timer Reset Inhibit Period		From falling edge of FLA register bits until flash sa		450		700	μs
		In 0.262s steps		0.262		1.049	
Torch Timer Range (Can be Disabled via I <sup>2</sup> C		In 0.524s steps		1.048		3.146	
Programming)		In 1.049s steps		3.145		7.340	s
<b>0 0</b> /		In 2.097s steps		7.340		15.729	
Torch Timer Accuracy				-10		+10	%
Open LED Protection Threshold		FLED1 enabled			V <sub>IN_FLED</sub> – 30mV		mV
Shorted LED Protection Threshold		FLED				1.0	V
FLED_ Short Debounce Timer		regulator is disabled – FL	From FLED_ short detected until FLED_ current regulator is disabled – FLED_ source is disabled after this timer to prevent excessive battery current				ms
FLED_ Open Debounce timer		regulator is disabled – IN	rom FLED_ open detected until FLED_ current egulator is disabled – IN_FLED voltage is mited to 5.8V max – FLED_ current source is		8		ms

## **LED Flash Driver EC Characteristics (continued)**

 $(V_{SYS} = 3.7V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
MAXFLASH						
Low SYS Detect Threshold Range		In 33mV steps	2.400		3.433	V
Low SYS Voltage Threshold Accuracy				± 2.5		%
Low SYS Voltage Hysteresis Programmable Range		In 100mV steps	100		300	mV
Low SYS Inhibit Timer			256		2048	ma
Low 515 Illilibit Timel		Rising in 256µs steps	256		2048	ms
Low SYS Inhibit Time Accuracy			-10		+10	%
FLASHEN, TORCHEN INF	PUTS					
Pulldown Resistor			400	800	1600	kΩ
Input Capacitance		(Note 3)		10		pF
Input Low Voltage	V <sub>IL</sub>				0.54	\ \
Input High Voltage	V <sub>IH</sub>		1.26			V

### **Safeout LDO**

 $(V_{DC}$  = 5V,  $V_{BATT}$  = 3.8V,  $T_{A}$  = -40°C to +85°C, unless otherwise noted. Typical values are at  $T_{A}$  = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
SAFEOUT						
		$5.0V < V_{DC} < 5.5V$ , $I_{SAFEOUT} = 10$ mA, SAFEOUT[1:0] = 01'b (default)	4.65	4.9	5.15	V
Output Voltage		SAFEOUT[1:0] = 00'b		4.85		V
(Default ON)		SAFEOUT[1:0] = 10'b		4.95		V
		SAFEOUT[1:0] = 11'b		3.3		V
Maximum Output Current			60			mA
Output Current Limit				150		mA
Dropout Voltage		V <sub>CHGIN</sub> = 5V, I <sub>OUT</sub> = 60mA		120		mV
Load Regulation		V <sub>CHGIN</sub> = 5.5V, 30μA < I <sub>OUT</sub> < 30mA		50		mV
Quiescent Supply Current		Not production tested		72		μA
Output Capacitor for Stable Operation (Note 3)		$0\mu A < I_{SAFEOUT} < 30mA$ , maximum ESR = $50m\Omega$	0.7	1		μF
Internal Off-Discharge Resistance				1200		Ω

# **White LED Backlight Driver**

 $(V_{SYS} = 3.7V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
STEP-UP WLED DRIVER				,			
Input Voltage Range				2.5		V <sub>OVLO</sub>	V
Step-Up Converter Quiescent Current		No switching, includes 20μA source	for each current		200		μA
Step-Up Converter Shutdown Current		V <sub>SYS</sub> = 5.2V, All current sou	rces disabled			1	μA
Current Source Quiescent Current		V <sub>WLEDOUT</sub> = 20V, change ir when 1 current source is ena			20		μA
Step-Up Converter Switching Frequency		BSTEN = 1, LEDPWM duty cycle > 0	WLEDFOSC = 00 WLEDFOSC = 11		0.667 1		MHz
Maximum Duty Cycle		WLEDFOSC[1:0] =11		93			%
Soft-Start Duration					10		V/ms
Output Voltage Range				V <sub>BAT</sub>		35	V
Overvoltage Protection Threshold			WLEDOVP = 1	34.1			
WLEDOUT Leakage Current		= 5.2V, boost in shutdown	T <sub>A</sub> = +25°C		0.12		μΑ
			T <sub>A</sub> = +25°C		2		μΑ
		V <sub>WLEDOUT</sub> = 35V, V <sub>WLEDL</sub> ) shutdown	( = 35V, boost in		25		μA
Current Source Linear Output Range		8-bit linear dimming range (9	97.656µA/LSB)	0		25	mA
Current Source Dropout Voltage		I <sub>WLED</sub> = 25mA (programme - V <sub>WLEDGND</sub> ) measured who dropped to 90% of full-scale V <sub>WLEDOOUT</sub> = 20V, T <sub>A</sub> = +2	en l <sub>LED_</sub> has programmed level,		100	180	mV
WLED Current Accuracy		I <sub>WLED</sub> = 25mA, V <sub>WLED</sub> = V <sub>WLEDGND</sub> , V <sub>WLEDOUT</sub> = 2	0.5V above 0V, T <sub>A</sub> = +25°C	-1		+1	%
WLED Current Matching		Mismatch between $W_{LED1}$ and $W_{LED2}$ , $I_{WLED} = 25\text{mA}$ , $(V_{WLED} - V_{WLEDGND}) = 0.5\text{V}$ , $V_{WLEDOUT} = 20\text{V}$ , $T_{A} = +25^{\circ}\text{C}$		-1		+1	%
WLED Leakage Current		V <sub>WLEDOUT</sub> = 35V,	T <sub>A</sub> = +25°C		0.1	1	μA
in shutdown		V <sub>WLED</sub> = 35V	T <sub>A</sub> = +85°C		1		μA
WLEDLX Leakage		V <sub>WLEDLX</sub> = 35V,	T <sub>A</sub> = +25°C	-5	+0.1	+5	μA
Current		V <sub>WLEDOUT</sub> = 35V	T <sub>A</sub> = +85°C		1		μA
N-Channel On- Resistance		I <sub>WLEDLX</sub> = 175mA			400		mΩ

## **White LED Backlight Driver (continued)**

 $(V_{SYS} = 3.7V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
N-Channel Current Limit		Current regulation mode	935	1100	1265	mA
WLED_ Voltage Regulation Maximum		(V <sub>WLED</sub> V <sub>WLEDGND</sub> ) below dropout voltage level of highest string		50		mV
WLED_ Voltage		Nonskip mode		125		mV
Regulation Window		Skip mode		487.5		mV
WLEDPWM Input Frequency Range		External PWM input	5		60	kHz
WLEDPWM Input Duty Cycle Range			0		100	%
WLEDPWM Input Current Dimming Range		PWM Duty = 0% to 100%	0		25	mA
WLEDPWM Input Current		V <sub>SYS</sub> = 2.5V to 5.2V, V <sub>WLEDPWM</sub> = 0V and 5.2V	-1		+1	μA
WLEDPWM Input Logic High		V <sub>SYS</sub> = 2.5V and 5.2V	1.2			V
WLEDPWM Input Logic Low		V <sub>SYS</sub> = 2.5V and 5.2V			0.4	V

# General, I<sup>2</sup>C, Logic, and Thermal

 $(V_{SYS} = 3.7V, V_{IO} = 1.8V, T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Shutdown Supply Current	I <sub>SYS</sub>	All circuits off		15	30	μA
SYS INPUT RANGE						
SYS Operating Voltage		Guaranteed by V <sub>SYSUVLO</sub> and V <sub>SYSOVLO</sub>	2.8		5	V
SYS Undervoltage Lockout Threshold (SYS UVLO)		V <sub>SYS</sub> falling, 200mV hysteresis	2.45	2.5	2.55	V
SYS Overvoltage Lockout Threshold (SYS OVLO)		V <sub>SYS</sub> rising, 200mV hysteresis	5.2	5.36	5.52	V
Low SYS Thresholds		Range programmable via LSDAC register, V <sub>SYS</sub> falling	2.60		3.35	V
Low SYS Hysteresis		Range programmable via LSHYST register	100		400	mV
THERMAL SHUTDOWN						
Thermal Shutdown Threshold		T <sub>J</sub> rising		165		°C
Thermal Shutdown Hysteresis				15		°C
Thermal Interrupt 1				120		°C
Thermal Interrupt 2				140		°C

# General, I<sup>2</sup>C, Logic, and Thermal (continued)

 $(V_{SYS} = 3.7V, V_{IO} = 1.8V, T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
LOGIC AND CONTROL IN	IPUTS						
SCL, SDA Input Low Level		T <sub>A</sub> = +25°C				0.3 x V <sub>IO</sub>	V
SCL, SDA Input High Level		T <sub>A</sub> = +25°C		0.7 x V <sub>IO</sub>			V
SCL, SDA Input Hysteresis		T <sub>A</sub> = +25°C			0.05 x V <sub>IO</sub>		V
SCL, SDA Logic Input Current		V <sub>IO</sub> = 3.6V		-10		+10	μA
SCL, SDA Input capacitance					10		pF
SDA Output Low Voltage		Sinking 20mA				0.4	V
Output Low Voltage RESET, INT		I <sub>SINK</sub> = 1mA				0.4	V
MRST Input Low Level		T <sub>A</sub> = +25°C				0.4	V
MRST Input High Level		T <sub>A</sub> = +25°C		1.4			V
MRST Input Hysteresis		T <sub>A</sub> = +25°C			0.1		V
MRST Input Current		V <sub>SYS</sub> = 5.5V	$T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	-2	0.1	+2	μΑ
Output High Leakage RESET, INT		V <sub>SYS</sub> = 5.5V	T <sub>A</sub> = +25°C T <sub>A</sub> = +85°C	-1	0	+1	μA
Interrupt Debounce Filter Timer		LOWSYS	<u> </u>		16		ms
RESET Deassert Delay					60		ms
					3		
					4		
Manual Reset Debounce				5 6			
		The period between	$(\overline{MRST} = Low)$ and				
Timer		automatic reboot start		7 (default)			s
				8			]
					9		
					10		

# General, I<sup>2</sup>C, Logic, and Thermal (continued)

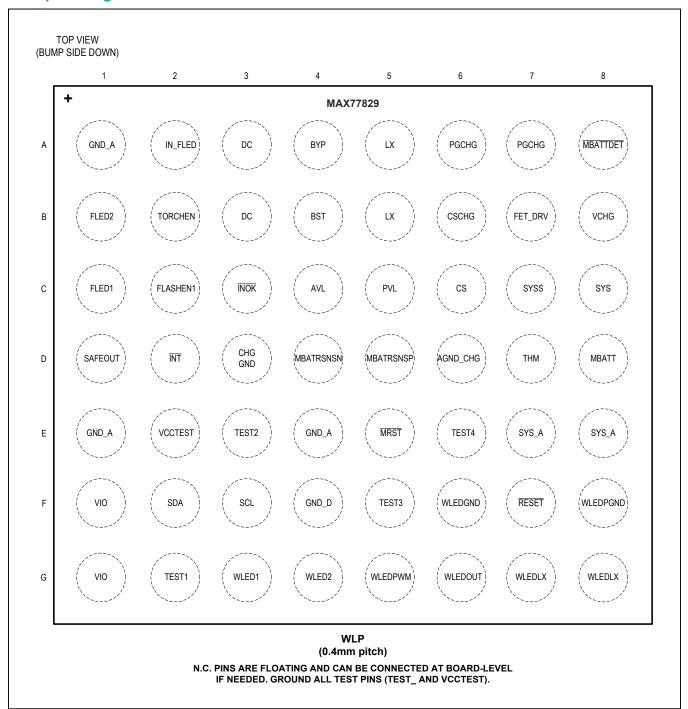
 $(V_{SYS} = 3.7V, V_{IO} = 1.8V, T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
I <sup>2</sup> C INTERFACE (Note 3)	'		<u>'</u>			
Clock Frequency			100		400	kHz
Bus-Free Time Between START and STOP			1.3			μs
Hold Time Repeated START Condition			0.6			μs
SCL Low Period			1.3			μs
SCL High Period			0.6			μs
Setup Time Repeated START Condition			0.6			μs
SDA Hold Time			0			μs
SDA Setup time			100			ns
Maximum Pulse Width of Spikes that Must be Suppressed by the Input Filter of Both SDA and SCL Signals				50		ns
Setup Time for STOP Condition			0.26			μs

Note 2: Limits are 100% tested at  $T_A$  = +25°C. Limits over the operating temperature range and relevant supply voltage range are guaranteed by design and characterization.

Note 3: Note production tested. Guaranteed by design.

# **Bump Configuration**



# Companion PMIC for Smartphone and Tablet

# **Bump Description**

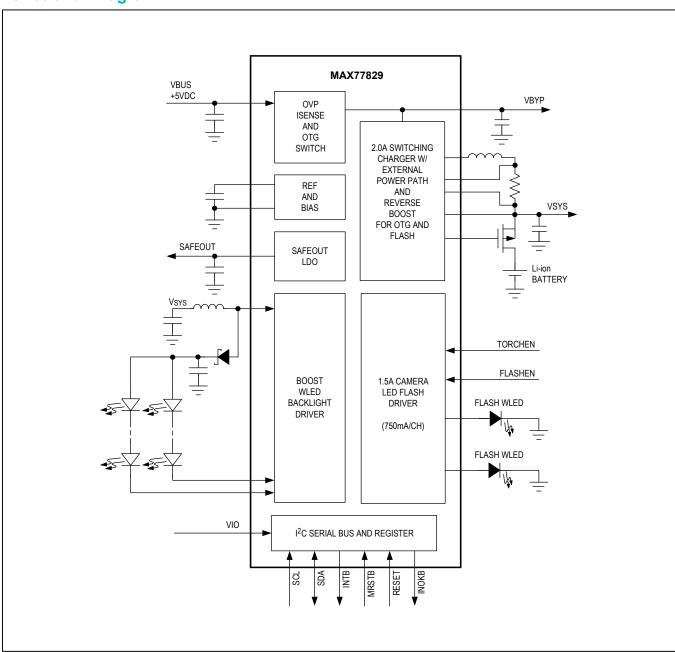
BUMP	NAME	FUNCTION
A3, B3	DC	High-Current Charger Input. Bypass to PGNDC with a 1µF/25V ceramic capacitor. Reverse Boost output.
A4	ВҮР	Connection Point Between Reverse Blocking MOSFET and High-Side Switching MOSFET.  Bypass to PGND with a 4.7µF/25V ceramic capacitor. Reverse boost regulation node.
A5, B5	LX	Buck/Boost Inductor Connection. Connect the inductor between LXCHG and CS.
A6, A7	PGCHG	Power Ground for Charger Step-Down Low-Side FET.
A8	MBATDET	Battery Detection Active-Low Input. Connect MBATDET to the ID pin on the battery pack. If MBATDET is pulled to ground, this indicates that the battery is present and the charger starts when valid DC power is present. MBATDET driven high or left unconnected indicates that the battery is not present and the charger will not start. MBATDET is pulled high to AVL through an internal 470kΩ resistor.
B4	BST	High-Side FET Driver Supply. Bypass BST to LXC with a 0.1µF ceramic capacitor.
В6	GSCHG	IC Substrate Ground
В7	FET_DRV	Battery FET Gate Driver
В8	VICHG	Charging Current Monitor
C3	INOK	Charger Input Valid Logic Output Flag. Open-drain, active-low output that indicates when valid voltage is present at both CHGIN and SYS. This signal is often needed by the main PMIC or the applications processor.
C4	AVL	Internal Bias Regulator Quiet Analog Bypass Pin. Internal $10\Omega$ connection between PVL and AVL forms LP filter with a $4.7\mu F$ external bypass capacitor to GNDCHG.
C5	PVL	Internal Bias Regulator High-Current Output Bypass Pin. Supports internal noisy and high-current gate drive loads. Bypass to PGNDCHG with a minimum 4.7µF ceramic capacitor.
C6	CS	Charger Current Sense Positive Terminal
C7	SYSS	Charger Current Sense Negative Terminal and System Voltage Sense Terminal
C8	SYS	System Power For Linear Charger. Boost supply during startup.
D3	CHGIND	Charging Status Indication. Open-drain, active-low output that indicates when the charging is active.
D4	MBATRSNSN	Battery Current Sense Negative Terminal
D5	MBATRSNSP	Battery Current Sense Positive Terminal
D6	AGND_CHG	Charger Analog Ground
D7	THM	Battery Thermistor Terminal/Battery Detection
D8	MBATT	Battery Positive Terminal. Bypass to AGND with a 4.7µF ceramic capacitor.
C1	FLED1	Flash LED Current Source Output 1. Connect FLED1 to the Anode of a high-brightness LED and Cathode tied to the ground plane. FLED1 has an internal TBDkΩ resistor to GND.
B1	FLED2	Flash LED Current Source Output 2. Connect FLED2 to the Anode of a high-brightness LED and Cathode tied to the ground plane. FLED2 has an internal TBDkΩ resistor to GND.

# Companion PMIC for Smartphone and Tablet

# **Bump Description (continued)**

BUMP	NAME	FUNCTION
A2	IN_FLED	Flash LED Driver Input. Bypass to GND with 4.7µF ceramic capacitor.
B2	TORCHEN	Torch Mode Enable Active-High Logic Input. TORCHEN has on-chip 800kohm pull-down resistor.
C2	FLASHEN1	Flash Strobe #1 Enable Active-High Logic Input. FLASHEN1 has an internal 800kΩ pull-down resistor.
D1	SAFEOUT	Safeout LDO Output. Default 4.9V and on when CHGIN power is valid. Bypass with a 1µF ceramic capacitor to GND.
F6	WLEDGND	Ground for WLED Current Drivers
F8	WLEDPGND	Power Ground for WLED Boost Converter
G3	WLED1	Current Source Output for WLED1 Boost Converter String. When powering series LEDs, the anode of the LED string should connect to LED.
G4	WLED2	Current Source Output for WLED2 Boost Converter String. When powering series LEDs, the anode of the LED string should connect to LED.
G5	WLEDPWM	Content-Based Adaptive Brightness Control Input for LED Boost Converter. WLEDPWM accepts a logic-level PWM signal with a frequency range of 5kHz to 60kHz.
G6	WLEDOUT	Boost Converter Overvoltage Sense Input. Bypass WLEDOUT to WLEDPGND with a 1µF ceramic capacitor.
G7, G8	WLEDLX	WLED Switching Node
D2	ĪNT	Interrupt Output. Active-low open-drain output.
E5	MRST	Manual Reset Input for Hardware Reset With Internal Timer
F1,G1	VIO	Digital I/O Supply Input for I <sup>2</sup> C Interface
F2	SDA	I <sup>2</sup> C Serial Data for MAX77829, Except the Fuel Gauge
F3	SCL	I <sup>2</sup> C Serial Clock for MAX77829, Except the Fuel Gauge
F7	RESET	Reset Output. Active-low open-drain output with timer. Provides manual reset capability to applications processors when the main PMIC is not already providing this function.
A1,E1 E4	GND_A	Analog Ground
E7, E8	SYS_A	Analog SYS Input. Share with SYS_Q
F4	GND_D	Digital Ground
E2	VCCTEST	Test Pin. Connect to ground.
E3	TEST2	Test Pin. Connect to ground.
E6	TEST4	Test Pin. Connect to ground.
F5	TEST3	Test Pin. Connect to ground.
G2	TEST1	Test Pin. Connect to ground.

# **Functional Diagram**



## Companion PMIC for Smartphone and Tablet

### **Detailed Description**

#### Main-Battery charger

The MAX77829 charger is a compact, high-frequency, high-efficiency switch-mode charger for a one-cell Lithium ion (Li+) battery with OTG capability and support to drive external p-channel MOSFET power-path. It delivers up to 2.0A of current to the battery from inputs up to 9.4V for DC and withstands transient inputs up to 22V. The typical 4MHz switch-mode charger is ideally suited for small portable devices such as headsets and ultra-portable media players because it minimizes component size and heat. The MAX77829 has programmable automatic input current limiting to protect upstream charging sources from collapsing. Upon request from the host processor, the MAX77829 can run its switching regulator in reverse to support USB 'On the Go' power, +5V at 500mA (default, up to 900mA with different factory setting).

The MAX77829 can manage two outputs independently, battery charging and system power. This allows immediate system operation under missing/deeply discharged battery conditions.

Battery protection features include low voltage prequalification, charge fault timer, die temperature monitoring, battery temperature monitoring and watchdog timer. The battery temperature monitoring adjusts the charge current and termination voltage for safe use of secondary lithiumion batteries.

#### **Features**

- Efficient 4MHz (typ) Switch Mode Charger Supporting 2.0A Charging Current Capability
- USB OTG Supports 500mA at +5V DC (Default Setting, up to 900mA with Different Factory Setting)
- External Power-Path P-MOSFET Driver for No/Dead Battery Support
- Digital Programming via I<sup>2</sup>C Interface:
  - Input Current Limit (Up to 2.0A)
  - Fast Charge Current (Up to 2.0A)
  - Termination Current
  - Restart Voltage
  - · Safety Timer/Watchdog Timer

- High-Accuracy Voltage and Current Regulation
- Input Current Regulation: ±5%(100mA, 500mA), ±10%(≥ 1A), Default 500mA
- Charger Voltage Regulation: ±0.5% 250C, Adjustable from 3.55V to 4.4V
- Fast Charge Current Regulation: 0.25A to 2.0A ±5%, Default 500mA
- 22V Absolute Maximum Input Voltage Rating
- Up to +9.4V Maximum Operating Input Voltage
- Input Voltage Based Automatic Input Current Limit (AICL)
- Battery/System Load Current Sensing and Limiting
- JEITA Compliance Thermistor Monitoring of Battery Temperature and Adjust Charging Current and Voltage
- Battery Protection:
  - Reverse Leakage Protection Prevents Battery Drainage
  - Input/Output Overvoltage Protection
  - · Battery Over Temperature Protection
  - Thermal Regulation and Shutdown
  - Battery Overcurrent Alarm
- System Voltage Regulator/Battery Charger with Power-Path:
  - External p-MOSFET Driver for Power-Path and Battery Charging
  - Supplement Mode to Delivery Current from Battery During Power -Path Operation
- Battery Presence Detection
- Interrupt Status Output
- Input/Output Overvoltage Protection
- Thermal Regulation Protection
- Charging Status Indicator

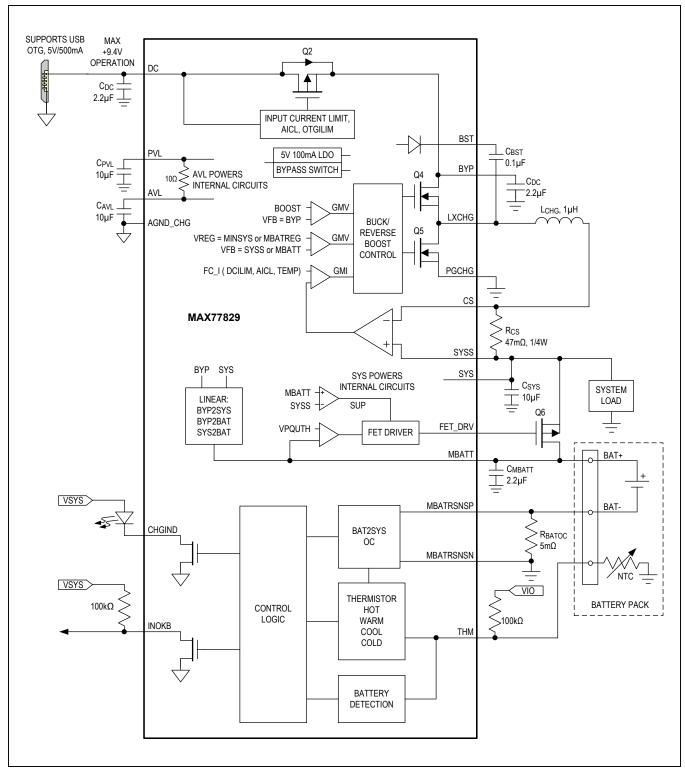


Figure 1. Main-Battery Charger Typical Application Circuit

#### **Inductor Selection**

The charger operates with a switching frequency of 4MHz and uses a 1µH or 2.2µH inductor. This operating frequency allows the use of physically small inductors while maintaining high efficiency. The inductor's DC current rating only needs to match the maximum load of the application because the MAX77829 features zero current overshoot during startup and load transients. For optimum transient response and high efficiency, choose an inductor with DC series resistance in the  $40 \text{m}\Omega$  to  $120 \text{m}\Omega$  range. See Table 1 below for suggested inductors and manufacturers.

### **MBAT Capacitor Selection (CMBATT)**

Choose the nominal MBAT capacitance ( $C_{MBATT}$ ) to be 2.2 $\mu$ F. The MBAT capacitor is required to keep the MBAT voltage ripple small and to ensure regulation loop stability. The MBAT capacitor must have low impedance at the switching frequency. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. For optimum load-transient performance and very low output voltage ripple, the MBAT capacitor value can be increased above 2.2 $\mu$ F.

As the case sizes of ceramic surface-mount capacitors decreases, their capacitance vs. DC bias voltage characteristic becomes poor. Due to this characteristic, it is possible for 0603 capacitors to perform well while 0402 capacitors of the same value perform poorly. The recommended nominal MBAT capacitance is  $2.2\mu F$ , however, after initial tolerance, bias voltage, aging, and temperature derating, the capacitance must be greater than  $1.5\mu F$ . With the capacitor technology that is available at the time the MAX77829 was released to production, the MBAT capacitance is best achieved with a single ceramic

capacitor (X5R or X7R) in a 0402 case size. The capacitor voltage ratings should be 6.3V or greater.

#### SYS Capacitor Selection (CSYS)

Choose the nominal SYS capacitance ( $C_{SYS}$ ) to be 10µF.  $C_{SYS}$  is the output capacitor for the step-down converter when charging. Alternatively,  $C_{SYS}$  is the input capacitor for the stepup converter when it is operating in OTG mode.  $C_{SYS}$  is required to keep the SYS voltage ripple small and to ensure regulation loop stability. In a typical application, SYS also powers many other elements the MAX77829 Power-SoC as well as system elements. Although the sum total of capacitance on SYS may be ~50µF it is critical that a local  $C_{SYS}$  is provided to reduce the current loops created by the DC-DC.

 $C_{SYS}$  must have low impedance at the switching frequency. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. For optimum load-transient performance and very low output voltage ripple, the MBAT capacitor value can be increased above10 $\mu$ F.

As the case sizes of ceramic surface-mount capacitors decreases, their capacitance vs. DC bias voltage characteristic becomes poor. Due to this characteristic, it is possible for 0603 capacitors to perform well while 0402 capacitors of the same value perform poorly. The recommended nominal  $C_{SYS}$  is  $10\mu F$ , however, after initial tolerance, bias voltage, aging, and temperature derating, the capacitance must be greater than  $6\mu F$ . With the capacitor technology that is available at the time the MAX77829 was released to production, the SYS capacitance is best achieved with a single ceramic capacitor (X5R or X7R) in an 0603 case size. The capacitor voltage ratings should be 6.3V or greater.

**Table 1. Suggested Inductors** 

MANUFACTURER	SERIES	INDUCTANCE (µH)	ESR (Ω)	CURRENT RATING (mA)	DIMENSIONS (mm)
Taiyo Yuden	MAKK2016	1	0.1	2500	2.0 x 1.6 x 1.0
TDK	TFA2016G	1	0.13	2500	2.0 x 1.6 x 1.0
TDK	MLP2520S	1.0	0.06	1500	2.0 x 2.5 x 1.0
TDK	VLS252012	1	0.105	2700	2.5 x 2.0 x 1.2
TOKO	MIPF2520	2.2	0.05	1500	2.5 x 2.0 x 1.0
TOKO	DFE252012C	1	0.06	2500	2.5 x 2.0 x 1.2
FDK	MIPSA2520D1R0	1.0	0.08	1500	2.5 x 2.0 x 1.2
Murata	LQM2HPN_G0	1.0	0.05	1600	2.5 x 2.0 x 0.6
Murata	LQM32PN1R0MG0	1	0.06	1800	3.2 x 2.5 x 0.9
Coilcraft	EPL2014	1.0	0.059	1600	2.0 x 2.0 x 1.4

### BYP Capacitor Selection (CBYP)

Choose the nominal BYP capacitance ( $C_{BYP}$ ) to be 2.2 $\mu$ F.  $C_{BYP}$  is the input capacitor for the step-down converter when charging. Alternatively,  $C_{BYP}$  is the output capacitor for the reverse boost converter. Larger value of  $C_{BYP}$  improves the decoupling for the DC-DC converter, but may cause high DC to BYP inrush currents when an input adapter is connected. To limit the inrush current,  $C_{BYP}$  must be no larger than 4.7 $\mu$ F.

 $C_{BYP}$  reduces the current peaks drawn from the input power source when charging. Similarly,  $C_{BYP}$  reduces the output voltage ripple of the stepup converter when it is operating in OTG mode. The impedance of the input capacitor at the switching frequency should be very low. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. To fully utilize the +22V input capability of the MAX77829, choose  $C_{BYP}$  to have a 25V or greater rating; many applications do not need to utilize the full input capability of the device and find that a 16V rating input capacitor is sufficient.

 $C_{BYP}$  is a critical discontinuous current path that requires careful bypassing. In the PCB layout, place  $C_{BYP}$  as close as possible to the power pins (BYP and PGCHG) to minimize parasitic inductance. If making connections to  $C_{BYP}$  through vias, ensure that the vias are rated for the expected input current so they do not contribute excess inductance and resistance between the bypass capacitor and the power pins. The expected  $C_{BYP}$  current is the same as the ISAT (see the *Inductor Selection* section).

 $C_{BYP}$  must meet the input ripple current requirement imposed by DC-DC converter. Ceramic capacitors are preferred due to their low ESR and resilience to surge currents. Choose the  $C_{BYP}$  capacitor so that its temperature rise due to ripple-current does not exceed approximately +10°C. For a step-down regulator, the maximum input ripple current is half of the output current. This maximum input ripple current occurs when the step-down converter operates as 50% duty cycle ( $V_{IN}$  = 2 x  $V_{BAT}$ ).

#### **BST Capacitor Selection (CBST)**

Choose the nominal BST capacitance ( $C_{BST}$ ) to be  $0.1\mu F$ .  $C_{BST}$  is part of a charge pump that creates the high-side gate drive for the DC-DC. If larger values of larger values of  $C_{BST}$  are used, ensure that CPVL is always 10 times larger than  $C_{BST}$ . The maximum expected working voltage of  $C_{BST}$  is the same as the PVL regulation voltage ( $\sim$ 5V). However, it is recommended that the  $C_{BST}$  has at least 10V rating. With the capacitor technology that is available at the time the MAX77829 was released to production, it is possible to find a 10V ceramic  $0.1\mu F$  0201

capacitor however these devices are pushing the limits, and a 10V ceramic  $0.1\mu F$  0402 may be more cost effective and readily available.

#### DC Input Capacitor Selection (C<sub>DC</sub>)

Choose the nominal DC capacitance ( $C_{DC}$ ) to be 2.2 $\mu$ F.  $C_{DC}$  is intended to decouple a charge source and its parasitic impedance. Typically, the charger source at DC is a USB connector's  $V_{BUS}$ . Larger values of  $C_{DC}$  improve the decoupling of the charger source impedance; however, take care not to exceed the maximum capacitance allowed by the USB specification (i.e.  $10\mu$ F and  $50\mu$ C). Note that for the USB input capacitance specification,  $C_{DC}$  is effectively in parallel with  $C_{BYP}$  and therefore the sum of these two capacitances should be less than  $10\mu$ F.

The impedance of the CDC at the DC-DC switching frequency should be very low. Ceramic capacitors with X5R or X7R dielectric are highly recommended due to their small size, low ESR, and small temperature coefficients. To fully utilize the +22V input capability of the MAX77829, choose CDC to have a 25V or greater rating; many applications don't need to utilize the full input capability of the device and find that a 16V or 10V rated input capacitor is sufficient.

#### **Charge Current Resistor Selection**

Both the top-off current range and fast charge current range depends on the sensing resistor (R<sub>SNS</sub>). The recommended resistor value is  $47m\Omega$  0.125W ±2%.

$$P_{RSNS} = I^2_{CHARGE} \times R_{SNS}$$
  
 $P_{RSNS} = (2.0A)^2 \times 0.047\Omega = 0.188W$ 

Calculate the CC mode charge current step from the CHGCC voltage setting and sense resistor as follows:

$$I_{CHARGE\_CURRENT\_STEP} = \frac{V(CHGCC)}{R_{SNS}}$$

<u>Table 2</u> below shows the charge current settings for two sensing resistors.

Table 2.Charge Current Settings for  $47m\Omega$  Sense Resistor

ВІТ	V <sub>I(REG)</sub> (mV)	$I_{CHARGE}$ (mA) $R_{SNS}$ = 47m $\Omega$
V <sub>(CHGCC&lt;11110&gt;)</sub>	70.5	1500
V <sub>(CHGCC&lt;10100&gt;)</sub>	47	1000
V <sub>(CHGCC&lt;01010&gt;)</sub>	23.5	500

Calculate the top-off charge current step as follows:

$$I_{CHARGE\_CURRENT\_STEP} = \frac{V(TOP\_OFF)}{R_{SNS}}$$

<u>Table 3</u> shows the top-off current settings for two sensing resistors.

### DC Input - Fast Hysteretic Step-Down Regulator

When a valid DC input is present, battery charging is supplied by the high-frequency step-down regulator from DC. The step-down regulation point is then controlled by three feedback signals: maximum step-down output current programmed by the input current limit, maximum charger current programmed for the fast charge current and maximum die temperature. The feedback signal requiring the smallest current controls the average output current in the inductor. This scheme minimizes total power dissipation for battery charging and allows the battery to absorb any load transients with minimum voltage disturbance.

A proprietary hysteretic current PWM control scheme ensures fast switching and physically tiny external components. The feedback control signal that requires the smallest input current controls the center of the peak and valley currents in the inductor. The ripple current is internally set to provide 4MHz operation. When the input voltage decreases near the output voltage, very high duty cycle occurs and, due to minimum off-time, 4MHz operation is not achievable. The controller then provides minimum off-time, peak current regulation. Similarly, when the input voltage is too high to allow 4MHz operation due to the minimum off-time, the controller becomes a minimum on-time, valley current regulator. In this way, ripple current in the inductor is always as small as possible to

Table 3. Top-off Current Settings for  $47m\Omega$  Sense Resistor

BIT	V <sub>(TOP-OFF)</sub>	$I_{(TOP-OFF)}(mA)$ R <sub>SNS</sub> = 47m $\Omega$
V <sub>(Top-off&lt;&gt;)</sub>	9.4	200
V <sub>(Top-off&lt;&gt;)</sub>	4.7	100
V <sub>(Top-off&lt;&gt;)</sub>	2.35	50

reduce ripple voltage on Battery for a given capacitance. The ripple current is made to vary with input voltage and output voltage in a way that reduces frequency variation. However, the frequency still varies somewhat with operating conditions.

#### Soft-Start

To prevent input current transients, the rate of change of the input current (di/dt) and charge current is limited. When the input is valid, the charge current ramps from 0mA to the fast-charge current value in 1.5ms. Charge current also soft-starts when transitioning from the prequalification state to the fast-charge state. There is no di/dt limiting when transitioning from the done state to the fast-charge state.

#### **PVL** and **AVL**

As shown in Figure 1, AVL is the output of a 5V/100mA linear regulator when power from BYP is available. If only power from SYS is available, then PVL is connected to SYS with a bypass switch. When AVL is greater than 2.7V the internal control circuits for the charger are enabled. Connect a  $10\mu\text{F}$  ceramic capacitor from AVL to AGND (CAVL). Powering external loads from AVL is acceptable, provided that they do not consume more than 100mA.

PVL powers the gate drivers and BST for the main-battery charger's step-down regulator, it also charges the BST capacitor. PVL is the filtered version of AVL. The filter consists of an internal  $10\Omega$  resistor and the PVL external bypass capacitor ( $10\mu F$ ). This filter creates a 100kHz lowpass filter that cleans the 4MHz switching noise from the analog portion of the MAX77829. Connect a  $10\mu F$  ceramic capacitor from PVL to PGCHG (CPVL). Powering external loads from PVL is NOT recommended.

#### Thermistor Input (THM)

The THM input connects to an external negative temperature coefficient (NTC) thermistor to monitor battery or system temperature. Charging is suspended when the thermistor temperature is out of range. The charge timers are suspended and hold their state but no fault is indicated. When the thermistor comes back into range, charging resumes and the charge timer continues from where it left. Connecting THM to GND disables the thermistor monitoring function.

Table 4. Suggested P-Channel MOSFET

MANUFACTURER	PART NUMBER PART DESCRIPTION		DIMENSIONS
Viohov	SiA443DJ	PFET, 20V, SC70 Power Pak	2.05mm x 2.05mm x 1.0mm = 4.2mm3
Vishay	Si4435DDY	PFET, 30V, SO-8	6.2mm x 5.0mm x 1.75mm
Fairchild	FDMA905P	PFET, 20V, SC70	2mm x 2mm x 1mm = 4mm3

Since the thermistor monitoring circuit employs an external bias resistor from THM to AVL, the thermistor is not limited only to  $10k\Omega$  (at  $25^{\circ}C$ ). Any resistance thermistor can be used as long as the value is equivalent to the thermistors  $+25^{\circ}C$  resistance. For example, with a  $10k\Omega$  at RTB resistor, the charger enters a temperature suspend state when the thermistor resistance falls below  $3.97k\Omega$  (too hot) or rises above  $28.7k\Omega$  (too cold). This corresponds to  $0^{\circ}C$  to  $+50^{\circ}C$  range when using a  $10k\Omega$  NTC thermistor with a beta of 3500K. The general relation of thermistor resistance to temperature is defined by the following equation:

$$R_{THRM} = R_{25} \times e^{\left(\beta \left(\frac{1}{T+273} - \frac{1}{298}\right)\right)}$$

Where:

 $R_{THRM}$  = resistance in  $\Omega$  of the thermistor at temperature T in °C.

 $R_{25}$  = resistance in  $\Omega$  of the thermistor at +25°C.

 $\beta$  = material constant of the thermistor, which typically ranges from 3000K to 5000K.

T = temperature of the thermistor in °C.

Some designs might prefer other thermistor temperature limits. Threshold adjustment can be accommodated by charging  $R_{TB}$ , connecting a resistor in series and/or in parallel with the thermistor, or using a thermistor with different B. For example, a +45°C hot threshold and 0°C cold threshold can be realized by using a thermistor with a B to 4250K and connecting  $120k\Omega$  in parallel. Since the thermistor resistance near 0°C is much higher than it is near +50°C, a large parallel resistance lowers the cold threshold, while only slightly lowering the hot threshold. Conversely, a small series resistance raises the cold

threshold, while only slightly raising the hot threshold. Raising  $R_{TB}$ , lowers both the hot and cold threshold, while lowering  $R_{TB}$  raises both thresholds.

Note that since AVL is active whenever valid input power is connected at DC, thermistor bias current flows at all times, even when charging is disabled. With a  $10k\Omega$  thermistor and a  $10k\Omega$  pullup to AVL, this results in an additional  $250\mu A$  load. This load can be reduced to  $25\mu A$  by instead using a  $100k\Omega$  thermistor and  $100k\Omega$  pull-up resistor.

#### **Thermal Foldback**

Thermal foldback maximizes the battery charge current while regulating the MAX77829 junction temperature. When the die temperature exceeds TREG, a thermal limiting circuit reduces the battery charge-current target until the charge current reaches 25% of the fast-charge current setting. The charger maintains 25% of the fast-charge current until the die temperature reaches TSHDN. Please note that the MAX77829 is rated for a maximum ambient temperature of +85°C. Furthermore, although the maximum die temperature of the MAX77829 is +150°C, it is common industry practice to design systems in such a way that the die temperature never exceeds +125°C. Limiting the maximum die temperature to +125°C extends long-term reliability.

#### **Boost Mode**

When enabled as a boost converter, in the absence of a valid charger input, the DC-DC converter is allowed to operate as a boost converter. The boost output voltage is regulated to 5.1V. The boost switches at 4MHz and is capable of delivering up to 500mA. The processor must enabled OTG mode by software via OTGEN bit. The reverse blocking switch allows the delivery of power to the charger input.

Table 5. Calculated Values for Different Thermistors

PARAMETER	VALUE						
R <sub>THM at</sub> T <sub>A</sub> = +25°C	10,000	10,000	10,000	47,000	47,000	100,000	100,000
Thermistor Beta (βΩ)	3380	3940	3940	4050	4050	4250	4250
$R_{TB(\Omega)}$	10,000	10,000	10,000	47,000	47,000	100,000	100,000
$R_{TP(\Omega)}$	OPEN	OPEN	301,000	OPEN	1,200,000	OPEN	1,800,000
$R_{TS(\Omega)}$	SHORT	SHORT	499	SHORT	2,400	SHORT	6,800
Resistance at T1_n15(Ω)	61,788	61,788	77,248	290,410	380,716	617,913	934,027
Resistance at T1_0(Ω)	29,308	29,308	31,971	137,750	153,211	293,090	343,283

### **Charger States**

The MAX77829 utilizes several charging states to safely and quickly charge batteries. Figure 2 shows an exaggerated view of a Li+/Li-Poly battery progressing through

the following charge states when the die and battery are close to room temperature: dead-battery  $\rightarrow$  precharge  $\rightarrow$  fast-charge  $\rightarrow$  top-off  $\rightarrow$  done.

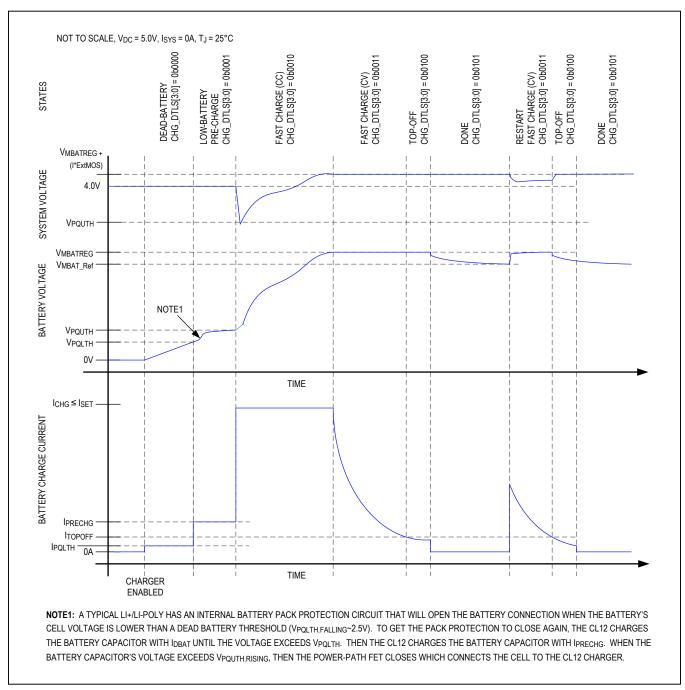


Figure 2. Li+/Li-Poly/LiFePO4 Charge Profile

### **Charger Disabled State**

When DC is low or the input voltage is out of range, the MAX77829 disables the charger. To exit this state, the input voltage must be within its valid range.

#### **Dead-Battery State**

When a deeply discharged battery is inserted with a voltage of less than  $V_{PQLTH}$ , the MAX77829 disabled the switching charger and linearly charges with  $I_{PQLTH}$ . Once  $V_{BAT}$  increases beyond  $V_{PQLTH}$ , the MAX77829 transitions to the precharge state. This state prevents the MAX77829 from dissipating excessive power in the event of a shorted battery.

### **Precharge State**

The precharge state occurs when the battery voltage is greater than  $V_{\mbox{\footnotesize{POLTH}}}$  and less than  $V_{\mbox{\footnotesize{POUTH}}}$ .

In this state, the dead-battery linear and system to battery linear charger turns on to provide  $I_{\mbox{\scriptsize PRECHG}}$  current to SYS. If the MAX77829 remains in this state for longer than  $t_{\mbox{\scriptsize PRECHG}}$ , then the MAX77829 transitions to the timer fault state. A normal battery typically stays in the prequalification state for several minutes or less and when the battery voltage rises above  $V_{\mbox{\scriptsize PQUTH}}$ , the MAX77829 transitions to the fast-charge constant current state.

### **Fast Charge Constant Current State**

The fast-charge constant current state occurs when the battery voltage is greater than  $V_{PQUTH}$  and less than  $V_{BATREG}$ . In this state, the switching charger is on and delivering current to the battery. The total battery current is IFC. If the MAX77829 remains in this state and the fast-charge constant voltage state for longer than  $t_{FC}$ , then the MAX77829 transitions to the timer fault state. When the battery voltage rises to  $V_{BATREG}$ , the MAX77829 transitions to the fast-charge constant voltage state. When JEITA is enabled (JEITA\_EN = 1), the fast-charge constant current is set to 50% of programmed value when -10°C < THM <15°C, and 100% of programmed value when 15°C < THM < 60°C.

The MAX77829 dissipates the most power in the fast-charge constant current state. This power dissipation causes the internal die temperature to rise. If the die temperature exceeds  $T_{REG}$ ,  $I_{FC}$  is reduced.

If there is low input voltage headroom ( $V_{DC}-V_{MBAT}$ ), then I  $_{FCHG}$  decreases due to the impedance from IN to BAT.

#### **Fast Charge Constant Voltage State**

The fast-charge constant voltage state occurs when the battery voltage is at the VMBATREG[3:0] and the charge current is greater than  $I_{DONE}.$  In this state, the switching charge is on and delivering current to the battery. The MAX77829 maintains  $V_{BATREG}$  and monitors the charge current to detect when the battery consumes less than the DONE current. When the charge current decreases below the  $I_{DONE}$  threshold, the MAX77829 transitions to the top-off state. If the MAX77829 remains in the fast-charge constant current state for longer than  $t_{FCHG}$ , then the MAX77829 transitions to the timer fault state.

#### **Top-Off State**

The top-off state occurs when the battery voltage is at  $V_{BATREG}$  and the battery current decreases below  $I_{DONE}$  current. In this state, the switching charger is on and delivers current to the battery. The MAX77829 maintains  $V_{BATREG}$  for a specified time. When this time expires, the MAX77829 transitions to the DONE state. If the charging current increases to  $I_{DONE}$  + 200mA before this time expires, then the charge reenters the fast-charge constant voltage state.

#### **Done State**

The MAX77829 enters its done state after the charge has been in the top-off state for topoff. In this state, the switching charger is off and no current is delivered to the battery. If the system load presented to the battery is low <<  $10\mu A$ , then a typical system can remain in the done state for many days. If left in the done state long enough, the battery voltage decays below the restart threshold ( $V_{MBAT\_REF}$ ) and the MAX77829 transitions back into the fast-charge state. There is no soft-start (di/dt limiting) during the done-to-fast-charge state transition.

#### **Timer Fault State**

The timer fault state occurs when either the prequalification or fast-charge timers expire. In this state, the charger is off. The charger can exit this timer fault state by cycling input power.

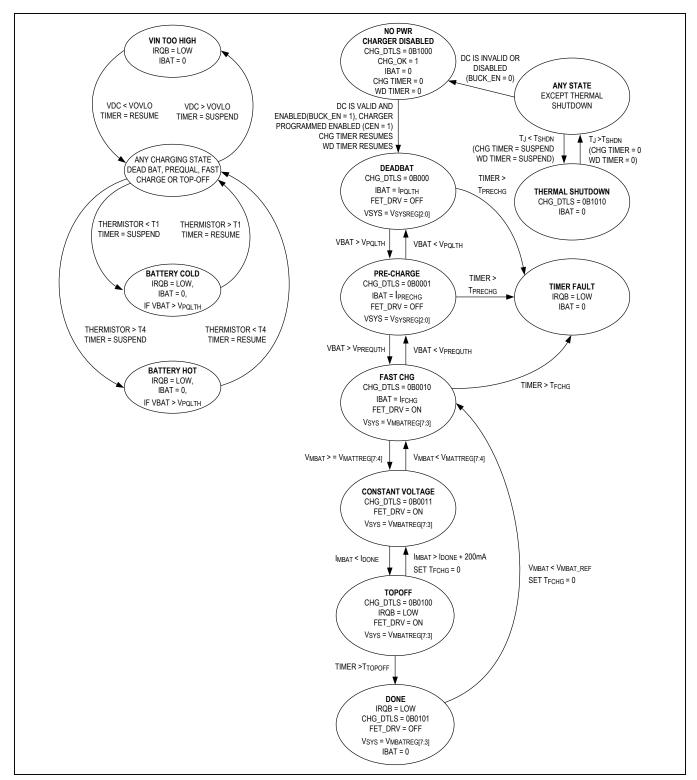


Figure 3. Charging State Diagram

#### **Input Current Limit**

The default settings of the  $I_{DC\_ILIM}$  control bits are such that when a charge source is applied to DC, the MAX77829 will turn on its DC-DC converter in BUCK mode, limit  $V_{SYS}$  to  $V_{SYSMIN}$ , and limit the charge source current to 500mA. All control bits are reset on global shutdown.

#### **Automatic Input Current Limit (AICL)**

The MAX77829 includes the Automatic Input Current Limit (AICL) feature for the DC input. The amplifiers required for sensing the currents and associated logic circuitry for making decisions and changing the battery-charger current are fully integrated in the ICs. This not only helps in reducing cost but also improves the speed of system response.

The MAX77829 AICL works by monitoring the current being drawn from DC and comparing it to the programmed current limit. The current limit is set based on the current-handling capability of the USB. Generally, this limit is chosen to optimally fulfill the system power requirements while achieving a satisfactory charging time for the batteries. If the AC-adapter current exceeds the set threshold, the charger responds by cutting back on the charger current, thereby keeping the current drawn from the AC adapter within the set limit. This AICL feature allows for reducing the AC adapter size and cost. The input current limit has two control inputs, one based on voltage and one based on current. The voltage input monitors the input voltage, and when it drops below the desired input (VDC\_AICL), it generates a flag (AICL) to decrement the fast-charge current.

When the voltage comparator initially trips at VDC\_AICL, fast-charge current decrements at a slow rate, allowing the charger output to settle until the voltage on DC returns above this voltage threshold. Once the DC voltage resolves itself, the current delivery of the adapter is maximized. In the event of a limited input current source, an example being a 500mA adaptor plugged into a 1A input current limit setting, a second voltage comparator set at VDC\_AICL - 100mV triggers and throttles the fast-charge current to a minimum of 75mA. Once the DC voltage corrects itself to above VDC AICL, the fast-charge level is

checked every 16ms to allow the system to recover if the available input power increases.

The current-limit input monitors the current through the input FET and generates a flag (DC\_I) to decrement the fast-charge current when the input limit is exceeded. The fast-charge current is slowly decremented until the input-limit condition is cleared. At this point, the fast-charge current is maintained for 16ms and is then sampled again.

#### **Battery Detection**

The MAX77829 charger detects insertion and removal of battery packs under various conditions. When a valid power source is detected on DC pin, the battery detection state machine is enabled. The first task is to determine the type of detection method used for predicting battery present condition. The voltage level on the MBATDET pin is used to determine the presence of either a low-cost battery or a smart battery.

### **JEITA Description**

The MAX77829 safely charges a single Li+ cell in accordance with JEITA specifications. The MAX77829 monitors the battery temperature while charging and automatically adjusts the fast-charge current and/or charge termination voltage as the battery temperature varies.

In safety region 1, the MAX77829 automatically reduces the fast-charging current for  $T_{MBATT} < +10^{\circ} C$  and reduces the charge termination voltage from 4.200V (±25mV) to 4.075V (±25mV) for  $T_{MBATT} > +45^{\circ} C$ . The fast-charge current is reduced to 50% of the nominal fast-charge current. When battery charge current is reduced by 50%, the timer is doubled.

In safety region 2, the IC automatically reduces the charge termination voltage from 4.200V ( $\pm 25$ mV) to 4.075V ( $\pm 25$ mV) for T<sub>MBATT</sub> <  $\pm 10$ °C and for T<sub>MBATT</sub> >  $\pm 45$ °C. The fast-charge current is not changed in safety region 2.

The customer can disable T2 and T3 temperature scaling for voltage and current by programming JEITA\_EN bit to disable (JEITA\_EN=0). In this case, only T1 and T4 temperature region will be enabled.

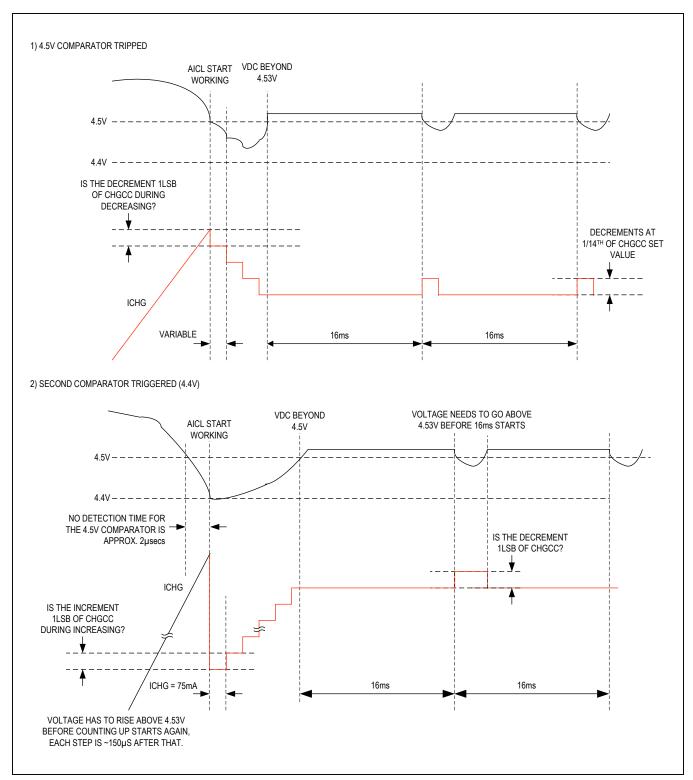


Figure 4. Automatic Input Current Limit Diagram

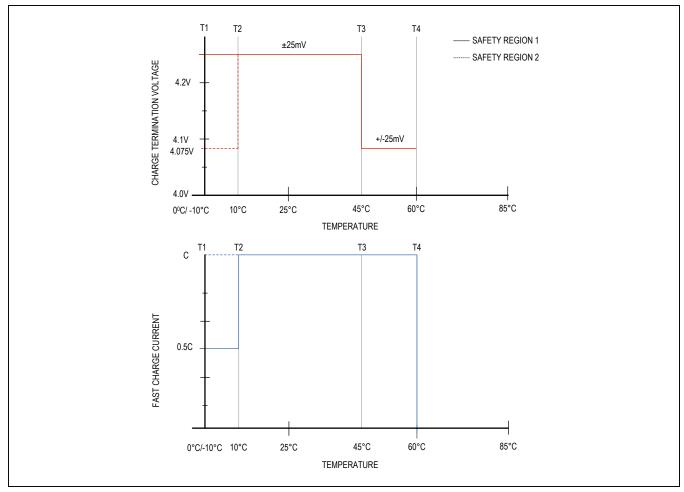


Figure 5. JEITA Safety Region

#### **LED Flash Driver**

### **Description**

The flash driver integrates an adaptive PWM step-up DC-DC converter (shared with switch-mode charger module) and two high-side current regulators cable of delivering up to 750mA/ch for flash applications and 187.5mA/ch for torch mode. A serial interface controls the step-up output voltage setting, the torch/flash current, and the torch/flash timers. When valid  $V_{DC}$  is present, flash LED driver operates only when  $V_{DC} < V_{DC}\ V$ .

#### **Features**

- Step-Up DC-DC Converter
  - Adaptive Regulation for Driving The LED Directly
  - · See the Charger Section for Feature List
- FLASH Current Regulator

- 2x High-Side Current Regulators Simplifies PCB Heat Sinking
- · Low Dropout Specification 160mV (typ) at 750mA
- I<sup>2</sup>C Programmable Flash Output Current (11.72mA to 750mA in 64 steps) Per Channel
- I<sup>2</sup>C Programmable Torch Output Current (11.72mA to 187.5mA in 16 steps) Per Channel
- Programmable Flash Safety Timer (62.5ms to 1000ms in 16 steps) – This Timer Cannot Be Disabled
- Programmable Torch Timer (262ms to 15.728s in 16 steps) – or Continuous Torch Current (Disable Option On The Torch Timer)
- MaxFlash System Lock-up Protection
- Open/Short LED Protection
- Dedicated FLASHEN and TORCHEN Inputs

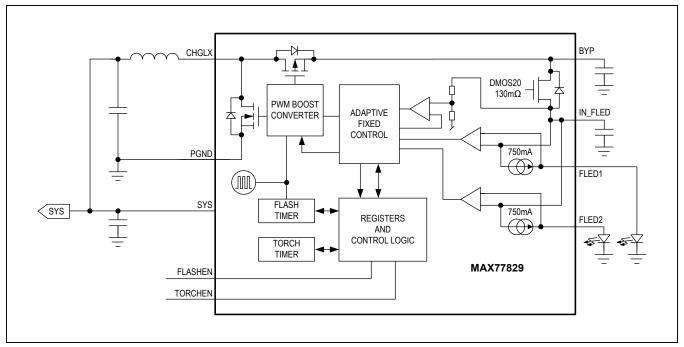


Figure 6. Functional Diagram for Charger Reverse Boost Converter and Current Sources

#### **Boost Converter**

The MAX77829 flash driver integrates an adaptive PWM step-up DC-DC converter (shared with switched mode charger module) and two high-side current regulators capable of delivering up to 750mA each, for flash applications. The serial interface controls individual output on/off, the step-up output voltage setting, the torch/flash current, and the torch/flash timer duration settings.

#### **Current Source (FLED1 and FLED2)**

The MAX77829 provides two high-side, low-dropout, linear current regulators. The LED current regulators can operate in either Torch or Flash mode. Each current source is programmable and regulated up to 375mA in Torch mode and up to 750mA in Flash mode. FLED current is programmable with 23.436mA/LSB resolution in Torch and Flash modes.

Torch mode can be enabled either using the serial interface or by logic control using the TORCHEN or FLASHEN inputs. See the description of the FLASH\_EN register for more information about programming the FLED enable behavior. Torch mode provides continuous lighting when enabled. The time duration is controlled through the Torch timer, enabling the user to limit the duration of torch light

from 0.262s to 15.73s, or enabled indefinitely, allowing the user to keep the LED on as long as a movie is being recorded.

Flash mode can also be enabled either using the serial interface or by logic control using the TORCHEN or FLASHEN inputs. See the description of the FLASH\_EN register for more information about programming the FLED enable behavior. Flash mode provides a limited-duration light pulse for camera functions. In Flash mode, the time duration is limited by an internal timer (FLASH\_TMR\_DUR[3:0]). See the *Flash Safety Timer* section for greater detail on this function. The output current in Flash mode is programmable from 23.436mA to 750mA. The settings above 625mA are allowed only if FLEDNUM = 0.

If both Flash and Torch modes are enabled at the same time, Flash mode is assigned with higher priority. Once the flash event is done, the current regulator will then return to torch mode, if this mode is still enabled via software.

When the flash LED current ramps up via (1) toggle FLASHEN or TORCHEN pins; (2) set TORCH\_FLED\_EN or FLASH\_FLED\_EN bits; (3) set TORCH\_I or FLASH\_I register values from a lower value to a higher value; atypical 12.5mA/µs of di/dt rate is applied on the flash LED current during the current transition.

#### Flash Mode

In Flash mode, each LED current source provides from 23.436mA to 750mA of output current. Flash mode can be enabled by driving FLASHEN or TORCHEN high or through the serial interface, depending on register settings. Flash duration is also programmable through the serial interface.

#### FLASHEN/TORCHEN

The FLASHEN or TORCHEN logic inputs or the serial interface can enable/disable the FLED\_ current regulator in Flash Mode and in Torch Mode.

If the FLED is enabled for both Torch and Flash mode at the same time, Flash mode has priority. Once the Flash safety timer expires, the current regulator then returns to Torch mode. If the safety timer is disabled, Torch mode current continues until disabled through the serial interface.

Configuring how the LED responds to FLASHEN or TORCHEN is accomplished by setting bits in the FLASH\_EN register.

#### Flash Safety Timer

The Flash safety timer is activated any time Flash mode is enabled. The Flash safety timer, programmable from 62.5ms to 1000ms via serial interface, limits the duration of Flash mode to the programmed Flash safety timer duration. This timer can be configured to operate either as a one-shot timer or maximum flash duration timer. In one-shot mode, the flash function is initiated on the rising edge of FLASHEN, TORCHEN, or the serial register bits and terminated based on the programmed value of the safety timer (see Figure 7). In maximum flash timer mode, flash function remains enabled as long as FLASHEN, TORCHEN, or the serial register command is high, unless the pre-programmed safety timer times out (see Figure 8).

Once Flash mode is disabled, by the FLASHEN or TORCHEN logic inputs, register command, or Flash safety timer, the flash must be off for a minimum flash debounce timer ( $500\mu s - 600\mu s$ ), before it can be reinitiated (see <u>Figure 11</u>). This prevents spurious events from re-enabling Flash mode. This time is described in the <u>Electrical Characteristics</u> table as the Flash Safety Timer Reset Inhibit Period.

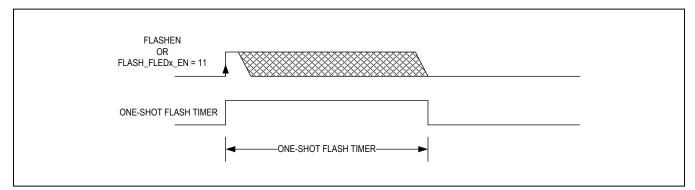


Figure 7. One Shot Flash Timer Mode

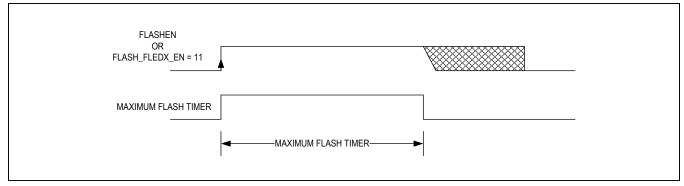


Figure 8. Maximum Flash Timer Mode

#### **Torch Mode**

In Torch mode, the LED current source provides from 11.72mA to 187.5mA of output current for each channel. Torch mode is enabled through the TORCHEN or FLASHEN inputs or through the serial interface. Torch mode duration is programmable through the serial interface, and can be programmed to remain on indefinitely.

#### **Enabling Torch Mode**

The current sources in Torch mode is independently enabled either through the TORCHEN or FLASHEN inputs or through the serial interface as programmed by the TORCH\_FLED\_EN bits in the FLASH\_EN register. If Flash mode and Torch mode are enabled at the same time, Flash mode is given the higher priority.

#### **Torch Safety Timer**

The Torch safety timer is activated any time Torch mode is enabled and the Torch Safety Timer Disable bit is set to 0.

The torch safety timer, programmable from 262ms to 15.7s via the serial interface, limits the duration of Torch mode to the programmed Torch safety timer duration. This timer can be configured to operate either in one-shot timer or maximum torch duration timer. In one-shot mode, the torch function is initiated on the rising edge of the TORCH\_FLED\_EN register bit or TORCHEN or FLASHEN inputs and terminated based on the programmed value of the safety timer (see Figure 10). In maximum torch timer mode, torch function remains enabled as long as TORCH\_FLED\_EN is a '11' or TORCHEN or FLASHEN is held high, unless the preprogrammed safety timer times out (see Figure 11).

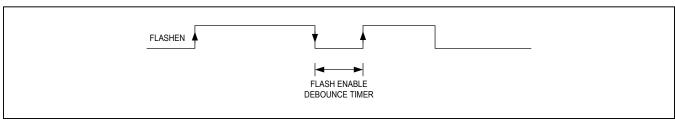


Figure 9. Flash Debounce Timer

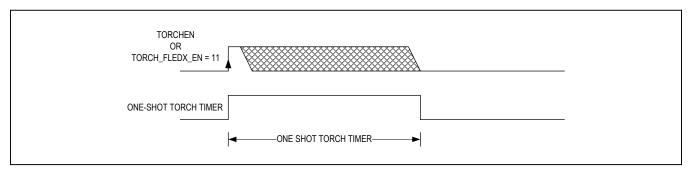


Figure 10. One Shot torch Timer Mode

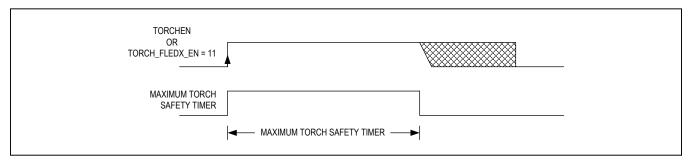


Figure 11. Maximum torch Timer Mode

The Torch safety timer can be disabled by setting the Torch safety timer disable bit to 1. In this case, the FLEDs will stay lit in Torch mode until the enable command (TORCHEN, FLASHEN, or serial interface) is deasserted, or Flash mode is initiated (since Flash mode has higher priority than Torch mode).

#### **MAXFLASH Function**

Note that MAXFLASH will detect a drop on  $V_{SYS}$  and not  $V_{BATT}$ .

During high load currents of a battery cell, the voltage will momentarily drop due to internal ESR of the battery, together with serial impendence form the battery to the load. For equipment requiring a minimum voltage for stable operation, the ESR of the battery needs to be calculated in order to estimate maximum current that can

be drawn from the battery without making the cell voltage drop below this critical threshold. If this is not done, the power-down voltage will have to be set artificial high, reducing run time of the battery-operated equipment.

For applications like camera flash, movie light, or torch light the ESR of the system needs to be measured to calculate the maximum current that can be consumed by the flash to insure that at the end of the flash the battery voltage has not dropped below the minimum required battery voltage for the remaining system.

Since the ESR of a battery cell is dependent on load current, temperature, age of cell, and other parameters this ESR measurement has to be done during the start of each event in order to ensure that the current ESR of the battery cell is correct.

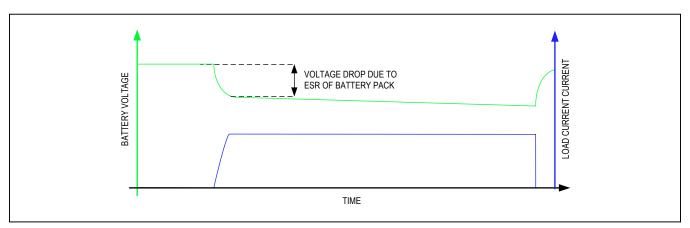


Figure 12. Voltage Drop Due to Battery ESR

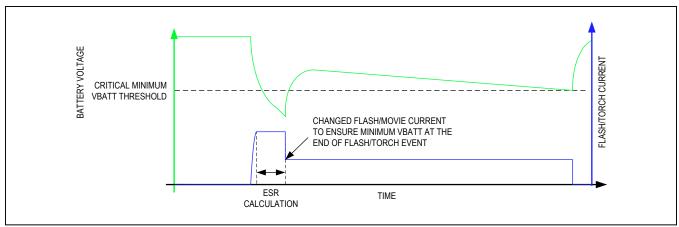


Figure 13. Using ESR Calculation to Insure Minimum Battery Voltage at the End of FLASH/TORCH Event Normal Case

In most cases, the camera flash is triggered by the camera module itself. Therefore, the ESR measurement of the battery has to be measured in real time during the initial flash event.

Since most systems contain many complex functions that are operated independent of each other, the current load might change during the FLASH/TORCH duration.

If another application within the system starts significantly drawing more current during the FLASH/TORCH duration, this can cause the battery voltage to drop below the minimum required battery voltage for the system, hence causing spurious events.

On the other hand, if an application is going from a high-current mode to a lower current mode during the FLASH/TORCH event, the battery voltage at the end of the FLASH/TORCH duration will be above the minimum battery voltage. This means that the actual FLASH/TORCH current could have been set higher for the remaining duration, allowing highest possible output current to be utilized.

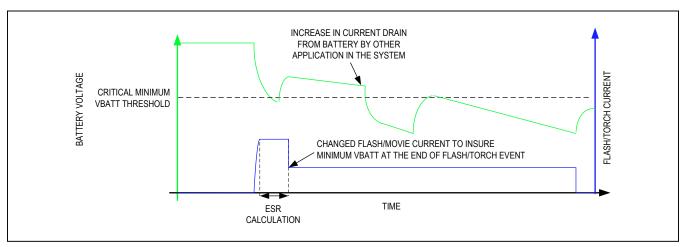


Figure 14. Using ESR Calculation to Ensure Minimum Battery Voltage at the End of FLASH/TORCH Event, with an Additional Load Event During the FLASH/TORCH Event

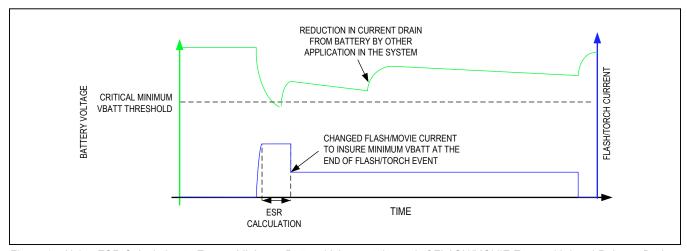


Figure 15. Using ESR Calculation to Ensure Minimum Battery Voltage at the end of FLASH/MOVIE Event with Load Release During FLASH/MOVIE Event

To avoid having to measure the ESR of the battery cell and still achieve the goal of insuring that the battery voltage does not drop below a predefined threshold, an alternative circuit can be used.

During a FLASH/TORCH event, the input voltage of the device is monitored (input Kelvin-connected to the battery cell, referred to as V<sub>BATT</sub>). If the input voltage drops below a predefined threshold, referred to as MAXFLASH\_TH, this is an indication that the FLASH/TORCH event is drawing more current than the battery can support.

As a reaction to this event, the current regulator driving the FLASH/TORCH will reduce output current in one step. This will reduce the input current, hence reducing the current drawn from the battery. Since the battery current is now reduced, VBATT will start to rise due to the internal ESR of the battery cell.

The current regulator will then implement a user-defined delay, referred to as  $t_{LB\_TMR\_F}$ , for falling edge detection and  $t_{LB\_TMR\_R}$  for rising edge detection. The  $V_{BATT}$  is then sampled again and compared to the MAXFLASH\_TH. If  $V_{BATT}$  is still below this MAXFLASH\_TH threshold the current regulator will reduce output current once again to insure that minimum  $V_{BATT}$  is available for the remaining of the system. If  $V_{BATT}$  is above the MAXFLASH\_TH threshold plus a user-defined hysteresis, referred to as

MAXFLASH\_HYS, the current regulator will increase the output current one step, only if present output current is less than user-defined output current. If the MAXFLASH\_HYS event is set to "000" then the flash current will only be reduced as a result of the low system voltage regardless if the voltage recovers again. The LED current is not allowed to increase again.

This will continue for the entire duration of the FLASH/TORCH event, ensuring that the FLASH/TORCH output current is always maximized for the specific operation conditions.

#### **Open/Short Protection**

The flash module monitors the FLED voltage to detect any open or short LEDs. An open fault is detected when the voltage on FLED rises above  $V_{BYP}-30\text{mV}$  (typ) for 8ms (typ), and short fault is detected when the voltage on FLED drops below 1.0V (max) (referenced to GND) for 1ms (typ). The fault detection provides a continuous monitor of the current regulator's status. Once a fault is detected, the current regulator is disabled and the status is latched into the interrupt register bit. This allows the processor to determine the operating condition of the MAX77829. Depending on the state of the interrupt mask bits, the MAX77829 can pull down on the  $\overline{\text{INT}}$  pin when the flash open/short interrupt occurs.

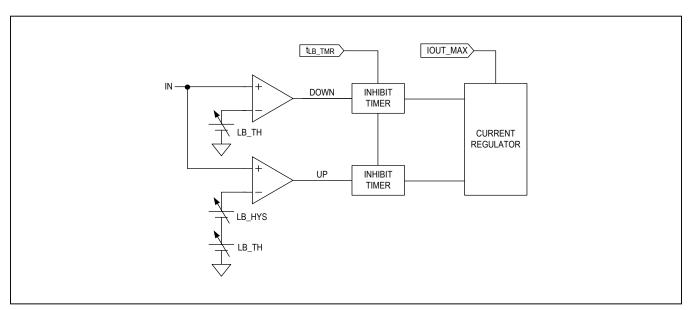


Figure 16. Block Diagram of MAXFLASH Function

#### Safeout LDO

The safeout LDO is a linear regulator that provides an output voltage of 3.3V, 4.85V, 4.9V, or 4.95V and can be used to supply low voltage-rated USB systems. The SAFEOUT linear regulator turns on when  $V_{CHGIN} \ge 3.2V$  and SFOUT\_EN = logic high (from MUIC), regardless of

Charger Enable or DETBAT. SAFEOUT is disabled when CHGIN is greater than the overvoltage threshold (5.90V typ). The safeout LDO integrate high-voltage MOSFET to provide 20V protection at their inputs, which are internally connected to the charger input at CHGIN.

SAFEOUT is default ON at 4.9V.

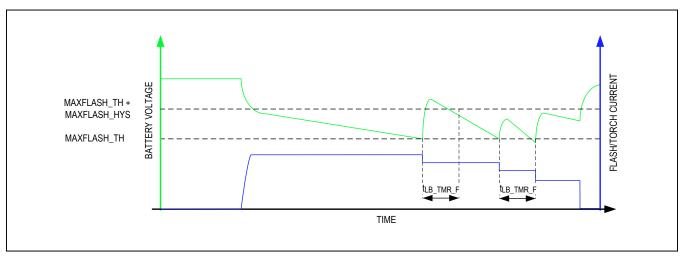


Figure 17. Example 1 of MAXFLASH Function Operation

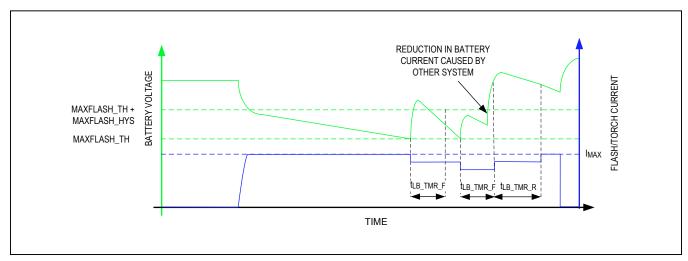


Figure 18. Example 2 of MAXFLASH Function Operation

### **WLED Backlight Driver**

#### **Step-Up Converter**

The MAX77829 LED boost converter operates from a 2.5V to  $V_{SYSOVLO}$  input supply. Due to duty-cycle limitations, full output power is only available for input voltages > 2.8V. For low input voltages (2.5V to 2.8V), maximum LED output current is available as shown in Table 6.

The MAX77829 LED boost converter utilizes a peakcurrent limited architecture. In the event of a serious overload, where the converter is operating at its current limit for 16ms, an interrupt is generated, and the processor can determine the appropriate course of action.

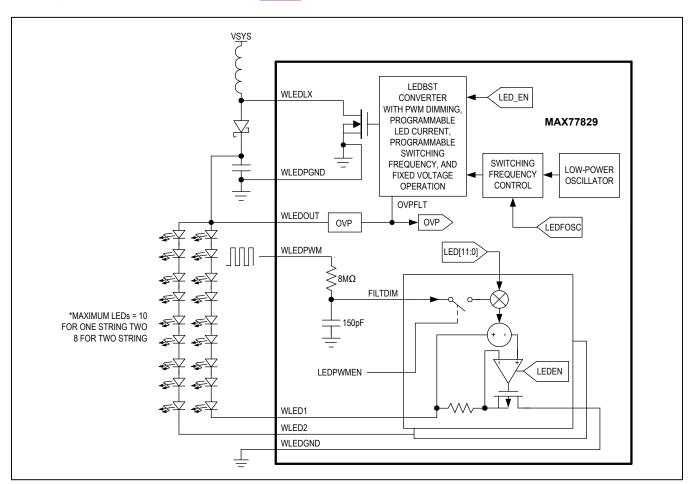


Figure 19. Functional Diagram for WLED Boost Converter and Current Source

**Table 6. Maximum LED Output Current** 

V	2 STRIN	GS OF 8	2 STRIN	GS OF 6	1 STRIN	G OF 10
$V_{SYS}$	1.47MHz	2.2MHz	1.47MHz	2.2MHz	1.10MHz	733kHz
3.0V	24.9mA	24.9mA	24.9mA	24.9mA	TBD	TBD
2.9V	24.9mA	21mA	24.9mA	24.9mA	TBD	TBD
2.8V	24.9mA	17mA	24.9mA	24.9mA	TBD	TBD
2.7V	23mA	14mA	24.9mA	24.9mA	TBD	TBD
2.6V	20mA	11mA	24.9mA	24.9mA	TBD	TBD
2.5V	18mA	8mA	24.9mA	21mA	TBD	TBD

The step-up converter switches at a fixed frequency of 2.2MHz to allow the use of small external components. Lower switching frequency can be selected through the serial interface to provide higher efficiency and/or avoid noise-sensitive frequency bands.

#### **Overvoltage Protection**

The MAX77829 is protected against open-circuited LED strings. In the event that the LED string is open, and the step-up converter is enabled, the WLEDOUT pin senses the output voltage of the step-up converter, and regulates the step-up output voltage at the OVP threshold. An interrupt (if unmasked) is generated when the step-up converter reaches the OVP threshold.

To optimize efficiency for the number of WLEDs used, the OVP threshold is programmable via WLEDOVP bit in WLEDBSTCNTL1 register. 28V (max) OVP setting is ideal for supporting up to 8 WLEDs in series while the 35V (max) OVP setting is needed for supporting up to 10 WLEDs in series.

#### **Current Sources**

The MAX77829 provides a low-side current source with 8-bit resolution for programming the LED current. A single register programs the output current in both sources. Both current sources can be programmed to respond to, or ignore, the WLEDPWM dimming input with a single bit.

The MAX77829 current source features a low-dropout voltage, increasing overall efficiency. When driving the maximum number of series LEDs, the current sources may enter dropout when the LED current is programmed near the maximum value. In this case, the current sources regulates with a 100mV (typ) voltage drop, and provide as much current as allowed by the forward voltage of the LEDs.

#### **Setting the Current Limit**

The two WLED Strings feature linear dimming with 8-bit resolution (97.656µA per LSB).

In addition to the internal LED current control offered through the MAX77829 step-up converter, an external PWM signal may be applied to the WLEDPWM input for content-adaptive brightness control. The WLEDPWM input accepts signals with frequency between 5kHz and 60kHz, although optimal performance (minimized LED current ripple) is attained with PWM frequencies ≥ 15kHz. The WLEDPWM input linearly decreases the LED current in strings 1 and 2 and is enabled through the serial interface.

WLED1 and WLED2 each have individual current sources, and both strings or any individual string may be enabled

at any time. WLED1 and WLED2 share a common current setting register, so strings 1 and 2 always have the same LED current, if enabled.

Mismatched LED strings can also be supported by the MAX77829. In the event that LED strings with different LED count are being powered at the same time, the string with the fewest number of LEDs will see a higher voltage drop across the current driver causing higher power consumption.

The WLED\_ current sources provide up to 24.9mA for powering the LED backlight. Under certain operating conditions, such as when powering the maximum number of LEDs in series, the WLED\_ current sources operates in a dropout condition, in which 24.9mA may no longer be provided to the LED string.

#### **Enabling CABC Dimming (WLEDPWM Input)**

The MAX77829 supports a CABC dimming signal from the processor to linearly decrease the backlight intensity based on the video signal content. The WLEDPWM input accepts a PWM signal in the 5kHz to 60kHz range, with optimal performance (minimized LED current ripple) attained for PWM dimming frequency > 15kHz. The WLEDPWM signal is internally RC filtered (corner frequency 500Hz), and is then used to decrease the reference voltage to the current DAC for strings 1 and 2. Two bits in Boost Converter Control Register 1 (LEDPWM1EN and LEDPWM2EN) independently program strings 1 and 2 to respond to or ignore the WLEDPWM signal. If one of the current sources (WLED1 or WLED2) is disabled, this current source ignores the WLEDPWM signal.

In the event that a 0% duty cycle is applied to the WLEDPWM input, the converter does not shut down, but instead continues to regulate the WLEDOUT voltage. The output current at the WLED pins is close to zero.

#### **Top System Management**

#### **Main Bias**

The main bias includes voltage and current references for all circuitry that runs from the  $V_{SYS}$  node. It includes a 0.3% accurate voltage reference that is used by various blocks. The current bias is generated from the reference voltage and trimmed to be within 1.5% and is zero-TC. The current bias is converted to a voltage to route to other blocks.

The  $V_{REF}$  block generates a 1.25V zero-TC reference voltage.  $I_{BIAS}$  takes  $V_{REF}$  as input and generates a  $V_{IBIAS}$  voltage that will track RPH variation and TC. Instead of generating a current output, a bias voltage for current is generated to be distributed to different blocks.

It saves the number of top level routing lines for bias current at the expense of requiring a bias current generation circuit, generating current as V<sub>IBIAS</sub>/RPH.

#### **System Faults**

The MAX77829 monitors the system for the following faults:

- SYS Undervoltage Lockout
- SYS Overvoltage Lockout
- SYS Low Threshold Detection
- Thermal Shutdown

#### **SYS Faults**

The system monitors the SYS node for undervoltage, overvoltage, and low threshold events. The following describes the IC behavior if any of these events is to occur. The SYS Low Threshold Detection is configurable via registers.

SYS undervoltage lockout prevents the regulators from being used when the input voltage is below the operating range. When the voltage from SYS to GND ( $V_{SYS}$ ) is less than the undervoltage lockout threshold ( $V_{SYSUVLO}$ ), the MAX77829 enters its global shutdown state.

SYS overvoltage lockout is a fail-safe mechanism and prevents the regulators from being used when the input voltage is above the operating range. The absolute maximum ratings state that the SYS node withstands is up to 6V. The SYS OVLO threshold is set to 5.3V (typ) – ideally  $V_{SYS}$ 

should not exceed the battery charge termination threshold. Systems must be designed such that  $V_{SYS}$  never exceeds 4.8V (transient and stead-state). If the  $V_{SYS}$  should exceed  $V_{SYSOVLO}$  during a fault, the MAX77829 enters its global shutdown state.

When  $V_{SYS}$  voltage falls below its low threshold ( $V_{SYSL}$ ), the MAX77829 initiates a LOWSYS interrupt. The low-SYS detection circuitry is enabled by default but can be disabled using the LSEN bit to reduce current consumption.  $V_{SYSL}$  is configurable using LSDAC register bits. Choose  $V_{SYSL}$  based on the system requirements and battery capacity.

The  $V_{SYSL}$  hysteresis ( $V_{LSHYST}$ ) is configurable using LHYST register bits. Choose  $V_{LSHYST}$  based on your system peak currents and battery impedance.  $V_{LSHYST}$  should be set sufficiently high to avoid oscillation in and out of the low-SYS state due to system peak currents.

Since the main battery is typically connected to the SYS node (through the internal BATT to SYS switch), this circuit also functions as a low BATT comparator.

#### **Thermal Fault**

The MAX77829 has one centralized thermal circuit for sensing die temperature. If temperature increases above 165°C (T<sub>SHDN</sub>) a thermal shutdown event occurs and the MAX77829 enters its global shutdown state.

In addition to the 165°C threshold, interrupts are generated when the die temperature reaches 120°C and 140°C.

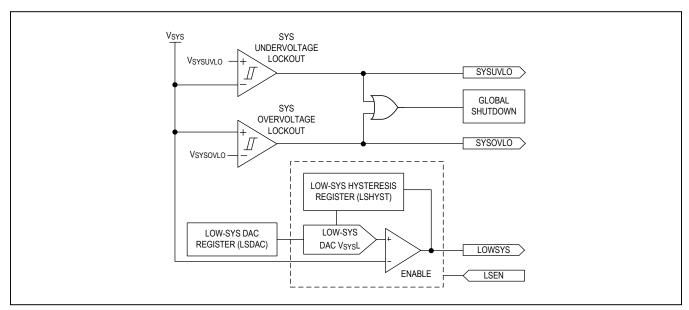


Figure 20. V<sub>SYS</sub> Fault Monitor Functional Block Diagram

There is a 15°C thermal hysteresis. After thermal shutdown, if the die temperature cools by 15°C, the thermal shutdown bus is deasserted and DVDD LDO can be enabled again.

The main battery charger has an independent thermal control loop which will not cause thermal shutdown. In the event that the charger thermal overload occurs, only the charger will turn OFF.

#### **Shutdown Events**

The MAX77829 has a POR bus that goes to all blocks except the fuel gauge. The POR signal turns off these blocks and resets their registers to a default state under the following conditions:

- SYS Undervoltage Lockout
- SYS Overvoltage Lockout
- Overtemperature Fault (165°C) This signal has hysteresis, if the die temperature hits 150°C, this signal is deasserted. This should not cause a turn-on event; turn-on events are listed in the <u>Thermal Fault</u> section. In other words, this signal is latched.

Manual Reset (MRST pulled low for 7s default).

#### I<sup>2</sup>C Interface

The I<sup>2</sup>C serial bus consists of a bidirectional serial-data line (SDA) and a serial-clock input (SCL). The IC is a slave-only device, relying upon a master to generate a clock signal. The master initiates data transfer to and from the IC and generates SCL to synchronize the data transfer.

I<sup>2</sup>C is an open-drain bus. Both SDA and SCL are bidirectional lines, connected to a positive supply voltage through a pullup resistor. They both have Schmitt triggers and filter circuits to suppress noise spikes on the bus to assure proper device operation. A bus master initiates communication with the IC as a slave device by issuing a START condition followed by the IC address. The IC address byte consists of 7 address bits and a read/write bit (R/W). After receiving the proper address, the IC issues an acknowledge bit by pulling SDA low during the ninth clock cycle. Figure 21 shows the I<sup>2</sup>C slave addresses for each functional block.

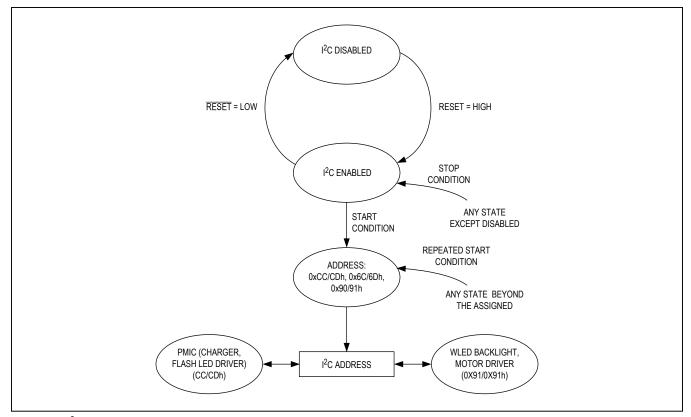


Figure 21. I<sup>2</sup>C State Diagram

#### I<sup>2</sup>C Bit Transfer

Each data bit, from the most significant bit to the least significant bit, is transferred one by one during each clock cycle. During data transfer, the SDA signal is allowed to change only during the low period of the SCL clock and it must remain stable during the high period of the SCL clock (Figure 22).

#### I<sup>2</sup>C Start And Stop Conditions

Both SCL and SDA remain high when the bus is not busy. The master signals the beginning of a transmission with a START (S) condition by transitioning SDA from high to low while SCL is high. When the master has finished communicating with the IC, it issues a STOP (P) condition by transitioning SDA from low to high while SCL is high. The bus is then free for another transmission (Figure 23). Both START and STOP conditions are generated by the bus master.

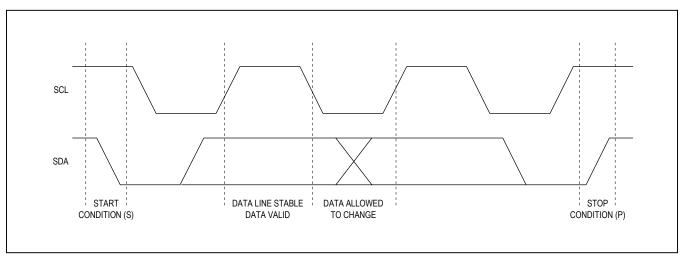


Figure 22. I<sup>2</sup>C Bit Transfer

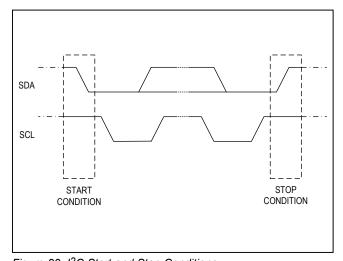


Figure 23. I<sup>2</sup>C Start and Stop Conditions

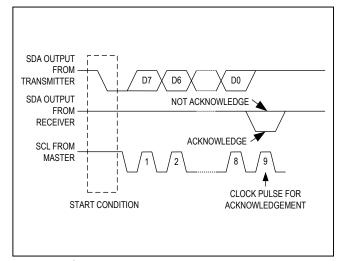


Figure 24. I<sup>2</sup>C Acknowledge

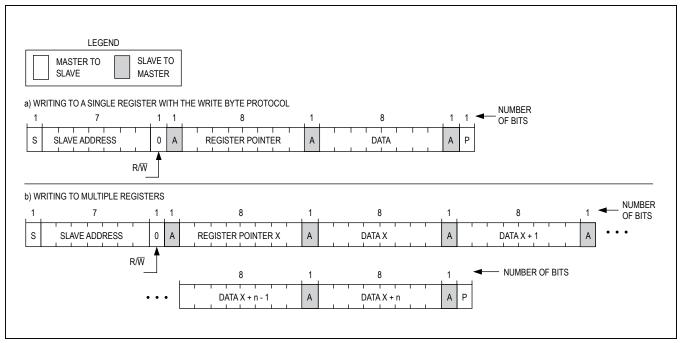


Figure 25. Master Transmits (Write Mode)

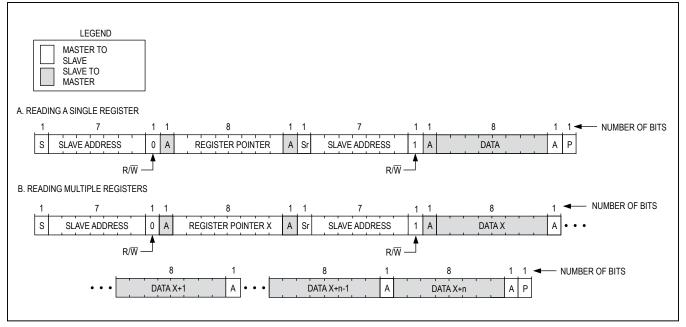


Figure 26. Master Reads Register Data Without Setting Register Address (Read Mode)

### I<sup>2</sup>C Acknowledge

The number of data bytes between the Start and Stop conditions for the Transmitter and Receiver are unlimited. Each 8-bit byte is followed by an acknowledge bit. The acknowledge bit is a high-level signal put on SDA by the transmitter during which time the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an acknowledge after each byte it receives. Also a master receiver must generate an acknowledge after each byte it receives that has been clocked out of the slave transmitter.

The device that acknowledges must pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable low during the high period of the acknowledge clock pulse (setup and hold times must also be met). A master receiver must signal an end of data to the transmitter by not generating an acknowledge on the last byte that has been clocked out of the slave. In this case, the transmitter must leave SDA high to enable the master to generate a Stop condition.

#### **Multibutton Manual Reset**

MRST is the manual reset input for hardware reset. Falling edge of MRST and minimum 7s (default) low initiate the automatic power reboot. The debouncing time is programmable ranging from 3s to 10s (with 1s per step). After the debouncing timer expires, the RESET output asserts and all the MAX77829 registers return to their

default values. The RESET output is intended to reset the host system's main PMIC and/or applications processor in case they do not already have manual reset inputs of their own. When the manual reset feature is not required, pull MRST above logic-high input.

#### INT

For example, if the application processor reads 0x02 from INTSRC register, it means the top-level PMIC block has an interrupt generated. The next step is to read the INT1 register of the PMIC functional block.

 $\overline{\text{INT}}$  becomes high (cleared) as soon as the read sequence of the last INT\_ register that contains an active interrupt starts. All interrupts can be masked to prevent  $\overline{\text{INT}}$  from being asserted for masked interrupts. A mask bit in the INTM register implements masking. The INTSRC register can still provide the actual interrupt status of the masked interrupts, but  $\overline{\text{INT}}$  is not asserted.

#### **Register Map**

### I<sup>2</sup>C Slave Address (W/R): 0xCC/0xCD

ADDR	REGISTER NAME	RESET TYPE	MODE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUE
0x00	IFLASH1	0	R/W		RESERVED			FLASH1_I[4:0]				0x00
0x01	IFLASH2	0	R/W		RESERVED			FLASH2_I[4:0]				
0x02	ITORCH	0	R/W		RESE	RVED			TORCH_I	OUT[3:0]		0x00
0x03	TORCH_TMR	0	R/W	TORCH_ TMR_MODE	DIS_TORCH_ TMR	RESE	RVED		TORCH_TMR_DUR[3:0]			0x00
0x04	FLASH_TMR	0	R/W	FLASH_ TMR_MODE		RESERVED			FLASH_TMF	R_DUR[3:0]		0x00
0x05	FLASH_EN	0	R/W	FLASH_FLE	ED1_EN[1:0]	FLASH_FLE	ED2_EN[1:0]	TORCH_FLI	ED1_EN[1:0]	TORCH_FLE	ED2_EN[1:0]	0x00
0x06	MAX_FLASH1	0	R/W	MAX_FL_EN		MA	X_FLASH_TH[4	4:0]		MAX_FLASI	H_HYS[1:0]	0x00
0x07	MAX_FLASH2	0	R/W	RESE	RVED LB_TMR_R[2:0] LB_TMR_F[2:0]					0x00		
0x08	MAX_FLASH3	0	R/W	FLED1_ MIN_MODE	RESERVED FLED1_MIN_OUT[5:0]					0x00		

# I<sup>2</sup>C Slave Address (W/R): 0xCC/0xCD (continued)

ADDR	REGISTER NAME	RESET TYPE	MODE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUE
0x09	MAX_FLASH4	0	R/W	FLED2_ MIN_MODE	RESERVED			FLED2_MIN	I_OUT[5:0]			0x00
0x0A	VOUT_CNTL	0	R/W	FLEDNUM		RESE	RVED		BOOS	T_FLASH_MOD	E[2:0]	0x00
0x0B	VOUT_FLASH	0	R/W	RESERVED			BOOS	T_VOUT_FLAS	VOUT_FLASH[6:0]			0x00
0x0E	FLASH_INT	S1	R/C	RESE	RESERVED FLED_FAIL MAX_FLA				FLED1_ OPEN	FLED2_ SHORT	FLED2_ OPEN	0x00
0x0F	FLASH_INT_ MASK	S1	R/W	RESE	RVED	FLED_ FAIL_m	MAX_ FLASH_m	FLED1_ SHORT_m	FLED1_ OPEN_m	FLED2_ SHORT_m	FLED2_ OPEN_m	0xFF
0x10	FLASH_ STATUS	S1	R		RESE	RVED	l	FLASH_ ON_STAT	TORCH_ ON_STAT	RESE	RVED	0x00
0x20	PMICID	0	R				ID[7	ː ':0]				0x29
0x21	PMICREV	0	R			VERSION[7:3]				REV[2:0]		0x01
0x22	INTSRC	S1	R/C		RESERVED		WLED_INT	RESERVED	FLASH_INT	TOP_INT	CHGR_INT	0x00
0x23	INTSRC_ MASK	S1	R/W		RESERVED		WLED_ INT_MASK	RESERVED	FLASH_ INT_MASK	TOP_ INT_MASK	CHGR_ INT_MASK	0xFF
0x24	TOPSYS_INT	S1	R/C		RESERVED			LOWSYS_ INT	RESERVED	T140C	T120C	0x00
0x26	TOPSYS_INT_ MASK	S1	R/W		RESE	RVED		LOWSYS_ INT_m	RESERVED	T140C_m	T120C_m	0xFF
0x28	TOPSYS_ STAT	0	R		RESE	RVED		LOWSYS_ STAT	MRSTB_ STAT	T140C_ STAT	T120C_ STAT	0x00
0x2A	MAINCTRL1	0	R/W		RESE	RVED		MREN	N	MRDBTMER[2:0]		0x0C
0x2B	LSCONFIG	S1	R/W	LSEN	LSHYS	ST[1:0]		LSDA	.C[3:0]		RESERVED	0x2A
0x30	CHGINT1	0	R/C	AICLOTG_I	TOPOFF_I	OVP_I	DC_UVP_I	CHG_I	BAT_I	THM_I	RESERVED	0x00
0x31	CHGINTM1	0	R/W	AICLOTG_M	TOPOFF_M	OVPM	DC_UVPM	CHG_M	BAT_M	THM_M	RESERVED	0xCE
0x32	CHGSTAT	0	R	AICL_NOK	DCI_NOK	OVP_NOK	DC_UVP_ NOK	CHG_NOK	BAT_NOK	THM_NOK	DC_V	0x00
0x33	DC_BATT_ DTLS	0	R	DC_AICL	DC_I	DC_OVP	DC_UVP	BAT_D	TLS[1:0]	BATDET_I	DTLS[1:0]	0x00
0x34	CHG_DTLS	0	R		THM_DTLS[2:0]		TOPOFF		CHG_D1	rls[3:0]		0x68
0x35	BAT2SYS_ DTLS	0	R		RESERVED		BAT2SYS	VPQUTH		RESERVED		0x00
0x36	BAT2SOC_ CTL	0	R/W	RESE	RVED	OTG_EN	BAT2S	OC[1:0]	BAT2SOCEN	TBAT2S	OC[1:0]	0x00
0x37	CHGCNTL1	С	R/W	SFO_DEBOUI	SFO_DEBOUNCE_TMR[1:0] SFO_DEBOUNCE_ EN			JEITA_EN	EITA_EN BUCK_EN CHGPRO		OT[1:0]	0x44
0x38	FCHGCRNT	С	R/W		FCHGTIME[2:0]			CHGCC[4:0]				0x46
0x39	TOPOFF	С	R/W	Т	TOPOFFTIME[2:0] RESE			RESERVED ITOPOFF[2:0]				0x63
0x3A	BATREG	С	R/W	REGTE	MP[1:0]	CHGRSTRT		MBATE	EG[3:0]		VICHG_ GAIN	0x16

# I<sup>2</sup>C Slave Address (W/R): 0xCC/0xCD (continued)

ADDR	REGISTER NAME	RESET TYPE	MODE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUE
0x3B	DCCRNT	С	R/W	RESE	RVED	VED DCILMT[5:0]					0x0C	
0x3C	AICLCNTL	С	R/W	RESERVED	AICLVTH	AICL_ RESET		AICL	[3:0]		DCMON_ DIS	0x0C
0x3D	RBOOST_ CTL1	D	R/W	BSTS	SOFTSLEWRATI	E[2:0]	RBFORCEPWM	1 RESERVED			RBOOSTEN	0x20
0x3E	CHGCNTL2	С	R/W	DCILIM_EN	PREQC	:UR[1:0]	CEN	QBATEN		VSYSREG[2:0]		0x36
0x3F	BATDET	0	R/W	STRONPUEN	BATDETENB			TDEB_BATREM			BAT_SIM_ DEB	0x6E
0x40	USBCHGCTL	С	R/W	DISTIMER		RESERVED		USB_ HICURRENT	USB_ SUSPEND	RESERVED	LOW_BAT	0x00
0x41	MBATREGMAX	0	R/W		RESE	RVED			MBATM	AX[3:0]		0x0F
0x42	CHGCCMAX	0	R/W		RESERVED			C	HGCCMAX[4:0]	]		0x1F
0x43	RBOOST_CTL2	D	R/W	RESERVED				VBYPSET[6:0]				0x00
0x44	CHGINT2	0	R/C	DC_V_I	RESE	RVED	CHG_ WDT_I		RESERVED		CHG_WDT_ WRN_I	0x00
0x45	CHGINTMSK2	0	R/W	DC_V_M	RESE	RVED	CHG_ WDT_M		RESERVED		CHG_WDT_ WRN_M	0x00
0x46	CHG_WDTC	0	R/W			RESE	RVED	,		CHG_WI	OTC[1:0]	0x00
0x47	CHG_WDT_ CTL	0	R/W	CHG_W	/DT[1:0] RESERVED				CHG_ WDT_EN	0x40		
0x48	CHG_WDT_ DTLS	0	R		RESERVED I I RESERVED I			CHG_WDT_ WRN_STAT	0x00			
0x4B	SAFEOUTCTL	0	R/W	RESERVED	SAFEOUT_ EN	RESERVED	ACTDISSAFEO1	RESE	RVED	SAFEO	UT[1:0]	0x51

\* R/W: Read and Write R: Read Only R/C: Read and Clear W/C: Write and Clear

# I<sup>2</sup>C Slave Address (W/R): 0x90/0x91

ADDR	REGISTER NAME	RESET TYPE	MODE	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	RESET VALUE
0x98	WLEDBST CNTL1	0	R/W	WLED1EN	WLED2EN	WLEDPWM1EN	WLEDPWM2EN	WLEDF	osc	WLEDOVP	RESERVED	0x00
0x99	IWLED	0	R/W				IWLED					0x00
0x9B	WLED_INT	S1	R/C	WLEDOVP	RES	SERVED	WLEDOL		RESI	ERVED		0x00
0x9C	WLED_INT_M	S1	R/W	WLED OVP_M	RES	RESERVED			RESI	ERVED		0x90

\* R/W: Read and Write R/C: Read and Clear

# Companion PMIC for Smartphone and Tablet

### **Register Introduction**

I<sup>2</sup>C Address:

The MAX77829 has 2 slave addresses. The least significant bit is the read/write indicator

• PMIC (Charger, Flash LED Driver): 0xCC/0xCD

• WLED Backlight Driver: 0x90/0x91

Register Reset Conditions:

- Type S1: Registers are reset each time when SYS < POR</li>
- Type O: Registers are reset each time when SYS 
   SYS UVLO or MAX77829 transitions from on to off state (global shutdown) or MRSTB is logic level low

### **PMIC Register Details**

#### **PMIC ID Register**

1	NAME	FUNCTION	ADDRESS	TYPE	RESET
Р	MICID	PMIC ID	0x20	0	0x29
BIT	MODE	NAME	NAME RESET DI		PTION
3:0	R	ID	1001	ID information	
7:4	R	ID	0010	ID IIIOIIIalioii	

#### **PMIC Version/Rev Register**

1	NAME	FUNCTION	ADDRESS	TYPE	RESET
PN	MICREV	PMIC Revision	0x21	0	0x01
BIT	MODE	NAME	RESET	DESCRIF	PTION
2:0	R	REV	001	Chip revision history	
7:3	R	VERSION	00000	Version information	

#### **Interrupt Source Mask Register**

1	NAME	FUNCTION	ADDRESS	TYPE	RESET
INTS	INTSRC_MASK Interrupt Ma		0x23	S1	0xFF
BIT	BIT MODE NAME		RESET	DESCRIF	PTION
0	R/W	CHGR_INT_MASK	1	Charger interrupt is masked.     Charger interrupt is unmasked.	
1	R/W	TOP_INT_MASK	1	Top interrupt is masked.     Top interrupt is unmasked.	
2	R/W	FLASH_INT_MASK	1	Flash interrupt is masked.     Flash interrupt is unmasked.	
3	R/W	RESERVED	1	Reserved	
4	R/W	WLED_INT_MASK	1	WLED interrupt is masked.     WLED interrupt is unmasked.	
5	R/W	RESERVED	1	Reserved	
6	R/W	RESERVED	1	Reserved	
7	R/W	RESERVED	1	Reserved	

# **Top SYS Interrupt Register**

N	AME	FUNCTION	ADDRESS	TYPE	RESET			
TOPS	SYS_INT	Top SYS Interrupts	0x24	S1 0x00				
BIT	MODE	NAME	RESET	DESCRIPTION				
0	R/C	T120C	0	+120°C Thermal Interrupt This interrupt is set when TDIE > +120°C. 1 = Detected 0 = Not detected				
1	R/C	T140C	0	+140°C Thermal Interrupt This interrupt is set when TDIE > +140°C. 1 = Detected 0 = Not detected				
2	R/C	RESERVED	0	Reserved				
3	R/C	LOWSYS_INT	0	Low SYS Interrupt 1 = Detected 0 = Not detected				
4	R/C	RESERVED	0	Reserved				
5	R/C	RESERVED	0	Reserved				
6	R/C	RESERVED	0	Reserved				
7	R/C	RESERVED	0	Reserved				

# **Top SYS Interrupt Mask Register**

1	NAME	FUNCTION	ADDRESS	TYPE	RESET		
	SYS_INT_ MASK	Top SYS Interrupt Mask	0x26	S1 0xFF			
BIT	MODE	NAME	RESET	DESCRIP	TION		
0	R/W	T120C_m	1	+120°C Thermal Interrupt Mask 0 = Not masked 1 = Masked			
1	R/W	T140C_m	1	+140°C Thermal Interrupt Mask 0 = Not masked 1 = Masked			
2	R/W	RESERVED	1	Reserved			
3	R/W	LOWSYS_INT_m	1	LOWSYS Event 0 = Not masked 1 = Masked			
4	R/W	RESERVED	1	Reserved			
5	R/W	RESERVED	1	Reserved			
6	R/W	RESERVED	1	Reserved			
7	R/W	RESERVED	1	Reserved			

**Top SYS Status Register** 

1	NAME	FUNCTION	ADDRESS	TYPE	RESET		
TOPS	SYS_STAT	Status 1	0x28	O 0x00			
BIT	MODE	NAME	RESET	DESCRIPTION			
0	R	T120C_STAT	0	+120°C Thermal Status 0 = T <sub>die</sub> < +120°C 1 = T <sub>die</sub> > +140°C			
1	R	T140C_STAT	0	+140°C Thermal Status 0 = T <sub>die</sub> < +140°C 1 = T <sub>die</sub> > +140°C			
2	R	MRSTB_STAT	0	Instantaneous Status on MRSTB Pir 0: MRSTB is Low 1: MRSTB is High	Without Debounce Timer		
3	R	LOWSYS_STAT	0	0: SYS is below the Low SYS thresh 1: SYS is above the Low SYS thresh			
4	R	RESERVED	0	Reserved			
5	R	RESERVED	0	Reserved			
6	R	RESERVED	0	Reserved			
7	R	RESERVED	0	Reserved			

# Main Control 1 Register

<b>N</b>	NAME	FUNCTION	ADDRESS	TYPE	RESET		
MAI	NCTRL1	Main Control 1	0x2A	0	0x0C		
BIT	MODE	NAME	RESET	DESCRIPTION			
2:0	R/W	MRDBTMER	100	Manual Reset Debounce Timer Whe 000: 3s 001: 4s 010: 5s 011: 6s 100: 7s 101: 8s 110: 9s 111: 10s	n MRSTB = Logic Low		
3	R/W	MREN	1	Manual Reset Enable Bit 0: Manual reset function is disabled. 1: Manual reset function is enabled.			
4	R/W	RESERVED	0	Reserved			
5	R/W	RESERVED	0	Reserved			
6	R/W	RESERVED	0	Reserved			
7	R/W	RESERVED	0	Reserved			

# **Low SYS Detection Configuration 1 Register**

ı	NAME	FUNCTION	ADDRESS	T	YPE	RE	SET
LS	SCNFG	Low SYS Detect Configuration	0x2B	S1 0x2A		x2A	
BIT	MODE	NAME	RESET		DESCRI	PTION	
0	R/W	RESERVED	0	Reserved			
					oltage that sets the 50mV steps from 2.		eshold.
				0000	2.60V	1000	3.00V
				0001	2.65V	1001	3.05V
4.4	D/M/	LSDAC	0101	0010	2.70V	1010	3.10V
4:1	R/W			0011	2.75V	1011	3.15V
				0100	2.80V	1100	3.20V
				0101	2.85V	1101	3.25V
				0110	2.90V	1110	3.30V
				0111	2.95V	1111	3.35V
6:5	R/W	LSHYST	01	Low SYS Comparator Hysteresis 00 = 100mV 01 = 200mV (default) 10 = 300mV 11 = 400mV			
7	R/W	LSEN	0	Low SYS DAC Enable With LSEN = 1, the low SYS DAC output is available as an interrupt. 0 = DAC disabled (reduce supply current). 1 = DAC enabled.			

# **Charger Register Details**

# **Charger Interrupt Register**

N	IAME	FUNCTION	ADDRESS	TYPE RESET	
CH	IGINT1	Charger Interrupt	0x30	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
0	R/C	RESERVED	0	Reserved	
1	R/C	THM_I	0	Thermistor Interrupt  0 = The THM_NOK status has not was read.  1 = The THM_NOK status has chawas read.	changed since the last time this bit
2	R/C	BAT_I	0	Battery Interrupt 0 = The BAT_NOK status or BATDET_DTLS<1:0>, or BAT2SYS or VPQUTH battery details has not changed since the last time this bit was read. 1 = The BAT_NOK status or BATDET_DTLS<1:0, or BAT2SYS or VPQUTH battery details has changed since the last time this bit was read.	
3	R/C	CHG_I	0	Charge Current Interrupt 0 = The CHG_NOK status has not changed since the last time this bit was read. 1 = The CHG_NOK status has changed since the last time this bit was read.	
4	R/C	DC_UVP_I	0	DC Undervoltage Interrupt 0 =The DCUVP_NOK status has not changed since the last time this bit was read. 1 = The DCUVP_NOK status has changed since the last time this bit was read.	
5	R/C	OVP_I	0	DC Overvoltage Interrupt 0 = The OVP_NOK status has not changed since the last time this bit was read. 1 = The OVP_NOK status has changed since the last time this bit was read.	
6	R/C	TOPOFF_I	0	Topoff Interrupt 0 = The topoff status has not changed 1 = The charger has entered topof	
7	R/C	AICLOTG_I	0	1 = The charger has entered topoff state.  AICL interrupt when buck and charger enabled.  OTGILIM interrupt when reverse boost enabled.  0 = The AICL_NOK or DCI_NOK status has not changed since the last time this bit was read (charger enabled).  The OTGILIM status has not changed since the last time this bit was read (reverse boost enabled).  1 = The AICL_NOK or DCI_NOK status has changed since the last time this bit was read (charger enabled).  The OTGILIM status has changed since the last time this bit was read (reverse boost enabled).	

# **Charger Interrupt Masks Register**

N	NAME	FUNCTION	ADDRESS	TYPE	RESET
CH	GINTM1	Charger INT MASK	0x31	0	0xCE
BIT	MODE	NAME	RESET	DESCRIP	TION
0	R/W	RESERVED	0	Reserved	
1	R/W	THM_M	1	Thermistor Interrupt Mask 0 = Unmask 1 = Mask	
2	R/W	BAT_M	1	Battery Interrupt Mask 0 = Unmask 1 = Mask	
3	R/W	CHG_M	1	Charger Interrupt Mask 0 = Unmask 1 = Mask	
4	R/W	DC_UVPM	0	DC Undervoltage Interrupt Mask 0 = Unmask 1 = Mask	
5	R/W	OVPM	0	DC Overvoltage Interrupt Mask 0 = Unmask 1 = Mask	
6	R/W	TOPOFF_M	1	Topoff Interrupt Mask 0 = Unmask 1 = Mask	
7	R/W	AICLOTG_M	1	AICL/OTG Interrupt Mask 0 = Unmask 1 = Mask	

# **Charger Status Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET	
СН	GSTAT	Charger Status	0x32	O 0x00		
BIT	MODE	NAME	RESET	DESCRIPTION		
0	R	DC_V	0	DC Voltage Status 1 = V <sub>DC</sub> > 5.9V 0 = V <sub>DC</sub> ≤ 5.9V		
1	R	THM_NOK	0	Thermistor Status Indicator. See the THM_DTLS [2:0] for more information.  A change in status issues an interrupt to THM_I.  1 = The thermistor temperature is outside of the allowable range for charging. THM_DTLS [2:0] = 0b001 or 0b101  0 = The thermistor temperature is inside of the allowable range for charging (i.e., okay). THM_DTLS [2:0] ≠ 0b001 or 0b101		
2	R	BAT_NOK	0	Single-Bit Battery Status Indicator. See BAT_DTLS [1:0] for more information.  A change in status issues an interrupt to BAT_I.  1 = The battery has an issue and the charger has been suspended.  BAT_DTLS [1:0] = 0b01 or 0b11  0 = The battery is okay. BAT_DTLS [1:0] = 0b10 or 0b00		
3	R	CHG_NOK	0	Single-Bit Charger Status Indicator. See CHG_DTLS [3:0] for more information.  A change in status issues an interrupt CHG_I.  1 = The charger has suspended charging. CHG_DTLS [3:0] = 0b0101 or 0b0110 or 0b0111 or 0b1001 or 0b1010  0 = The charger is okay. All other CHG_DTLS [3:0] states.		
4	R	DC_UVP_NOK	0	A change in status issues an interru 1 = The DC UVP is invalid. DC_UV 0 = The DC UVP input is valid. DC_	P = 0	
5	R	OVP_NOK	0	A change in status issues an interru 1 = The DC input is invalid. DC_OV 0 = The DC input is valid. DC_OVP	P	
6	R	DCI_NOK	0	A change in status issues an interrupt to AICL_I.  1 = The DC input current limit is invalid. DC_I = 1  0 = The DC input is valid. DCI = 0		
7	R	AICL_NOK	0	A change in status issues an interru 1 = The part is operating in AICL me	AICL Input Status Indicator. See DC Details for more information.  A change in status issues an interrupt to AICL_I.  1 = The part is operating in AICL mode.  0 = The part is not operating in AICL mode.	

# DC and BATT Details Register

	NAME	FUNCTION	ADDRESS	TYPE	RESET
DC_B	BATT_DTLS	Details 1	0x33	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
1:0	R	BATDET_DTLS [1:0]	00	BATDET_DTLS generates an interrupt to the processor BAT_I. Battery Detect Details: 01,10 = Battery detected 11 = BAT_REMOVED detected 00 = CONTACT_BREAK	
3:2	R	BAT_DTLS [1:0]	00	Battery Details  00 = V <sub>MBATT</sub> < V <sub>PQLTH</sub> . This condition is also reported in the CHG_DTLS [3:0] as 0000.  01 = The battery is taking longer than expected to charge. This could be due to high system currents, an old battery, a damaged battery or something else. Charging has suspended and the charger is in its timer fault mode. This condition is also reported in the CHG_DTLS [3:0] as 0110.  10 = The battery is okay.  11 = The battery voltage is greater than the battery overvoltage flag threshold (VBAT_OVP), VBAT_OVP is set to a fixed LSB value above battery regulation target. Note that this flag is only generated when there is a valid DC input.	
4	R	DC_UVP	0	DC Details. An invalid condition indicates adapter removed/ unplugged. A valid condition indicates adapter inserted.  1 = V <sub>DC</sub> is valid. V <sub>DC</sub> > VDC_UVLO  0 = V <sub>DC</sub> is invalid. V <sub>DC</sub> < VDC_UVLO	
5	R	DC_OVP	0	DC Details $0 = V_{DC}$ is valid. $V_{DC} < VDC_OVLO$ $1 = V_{DC}$ is invalid. $V_{DC} > VDC_OVLO$	
6	R	DC_I	0	DC Details 0 = IDC is valid. IDC < Input Current Limit 1 = IDC is invalid. IDC > Input Current Limit	
7	R	DC_AICL	0	DC AICL Details 0 = V <sub>DC</sub> > AICL threshold. 1 = V <sub>DC</sub> < AICL threshold.	

# **Charger Details Register**

	NAME	FUNCTION	ADDRESS	TYPE RESET		
CH	HG_DTLS	Details 2	0x34	O 0x68		
BIT	MODE	NAME	RESET	DESCRI	PTION	
3:0	R	CHG_DTLS [3:0]	1000	Charger Details  0000 = Charger is in dead-battery region, V <sub>BAT</sub> < V <sub>PQLTH</sub> , T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> ,  0001 = Charger is in precharge mode, V <sub>BAT</sub> < V <sub>PQUTH</sub> , T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> ,  0010 = Charger is in fast-charge constant current mode, V <sub>BAT</sub> > V <sub>PQUTH</sub> , T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> ,  0011 = Charger is in fast-charge constant voltage mode, V <sub>BAT</sub> = V <sub>BATREG</sub> , T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> 0100 = Charger is in top-off mode, V <sub>BAT</sub> > V <sub>BATREG</sub> , T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> 0101 = Charger is in done mode, V <sub>BAT</sub> > V <sub>BATREG</sub> and T > T <sub>TOPOFF</sub> + 16s, T <sub>J</sub> < T <sub>JREG</sub> , T <sub>J</sub> < T <sub>JSHDN</sub> 0110 = Charger is in timer fault mode, V <sub>BAT</sub> < V <sub>MBATOV</sub> , T T <sub>J</sub> < T <sub>JSHDN</sub> 0111 = Charger is in temperature suspend mode, see THM_DTLS  [2:0]  1000 = Buck off, charger off  1001 = Charger is in precharge, fast-charge or top-off modes and is operating with its thermal loop active (i.e., the junction temperature is greater than the value set by REGTEMP [1:0]).  1010 = Charger is off and junction temperature is > T <sub>SHDN</sub> 1011 = Buck on, charger off  1100 = Charger OTG current limit is exceeded longer than debounce time  1101 = USB suspend		
4	R	TOPOFF	0	TOPOFF Details A change in details entering topoff issues an interrupt to TOPOFF_I but not exiting.  0 = TOPOFF is not reached; I <sub>FCHG</sub> > IDONE  1 = TOPOFF is reached; I <sub>FCHG</sub> < IDONE		
7:5	R	THM_DTLS [2:0]	011	Thermistor Details  001 = Low temperature and chargin  010 = Low temperature charging (country)  011 = Standard temperature charging (country)  100 = High temperature charging (country)	cool, > T1 and < T2) ing (normal, >T2 and <t3) warm, &gt;T3 and <t4)< td=""></t4)<></t3) 	

# **Battery Overcurrent, Prequal Details Register**

	NAME	FUNCTION	ADDRESS	TYPE RESET	
BAT2	SYS_DTLS	Details 3	0x35	0	0x00
BIT	MODE	NAME	RESET	DESCRIP	TION
2:0	R	RESERVED	0	Reserved	
3	R	VPQUTH	0	Prequal Upper Threshold Detail  0 = MBATT< V <sub>PQUTH</sub> 1 = MBATT> V <sub>PQUTH</sub> , or no valid charger.	
4	R	BAT2SYS	0	Battery Overcurrent Detail 0 = The battery current does not exceed overcurrent threshold. 1 = The battery has been overcurrent for at least t <sub>BAT2SOC</sub> .	
7:5	R	RESERVED	000	Reserved	

# **Battery-to-System Overcurrent Control Register**

	NAME	FUNCTION	ADDRESS	TYPE RESET		
BAT	2SOC_CTL	BAT2SYS OC Control	0x36	O 0x00		
BIT	MODE	NAME	RESET	DESCI	RIPTION	
1:0	R/W	TBAT2SOC [1:0]	00	Battery Overcurrent Debounce Ti 00 = 4ms 01 = 6ms 10 = 8ms 11 = 10ms	me	
2	R/W	BAT2SOCEN	0	Battery to System Overcurrent Enable 0 = Disable 1 = Enable		
4:3	R/W	BAT2SOC [1:0]	00	Battery Overcurrent Threshold 00 = 3.0A (20mV) 01 = 3.5A (25mV) 10 = 4.0A (27.5mV) 11 = 5.0A (30mV)		
5	R/W	OTG_EN	0	OTG Enabled Control 0 = OTG disabled 1 = OTG enabled		
7:6	R/W	RESERVED	000	Reserved		

# **Charger Control 1 Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
CH	HGCNTL1	Charger Control 1	0x37	С	0x44
BIT	MODE	NAME	RESET	DESCRIPTION	
1:0	R/W	CHGPROT [1:0]	0	Charger Settings Protection Bits. Writing "11" to these bits unlock the settings for the above registers. Writing any value besides "11 locks these registers.  00 = Locked  01 = Locked  10 = Locked  11 = Unlocked	
2	R/W	BUCK_EN	1	Buck Enable/Disable Bit 0 = Buck disabled 1 = Buck enabled	
3	R/W	JEITA_EN	0	JEITA Enable Configuration, JEITA enable bit does not affect T1 and T4 temperature sensing.  0 = JEITA is enabled 1 = JEITA is disabled	
4	R/W	THM_DIS	0	Thermistor Enable/Disable 0 = Thermistor is enabled 1 = Thermistor is disabled	
5	R/W	SFO_ DEBOUNCE_EN	0	SAFEOUT LDO Debounce Timer Enable/ 0 = Disabled (default) 1 = Enabled	Disable
7:6	R/W	SFO_ DEBOUNCE_ TMR [1:0]	01	SAFEOUT LDO Debounce Timer. If CHGIN voltage falls below its UVLO- and recovers above its UVLO+ threshold within the debounce timer, SAFEOUT LDO output is not disabled. Note this timer, when enabled, only applies on the CHGIN falling edge. Whe CHGIN rises, the SAFEOUT LDO output is enabled as soon as the CHGIN input is valid, no debounce time in such case.  00 = 50ms 01 = 100ms (default) 10 = 150ms 11 = 200ms	

# **Fast Charge Current and Timer Control Register**

	NAME	FUNCTION	ADDRESS	TYPE RESET	
FC	HGCRNT	Fast Charge Current	0x38	C (Protected with CHGPROT) 0x46	
BIT	MODE	NAME	RESET	DESCI	RIPTION
4:0	R/W	CHGCC [4:0]	00110	Fast-Charge Current Selection. When the charger is enabled, the charge current limit is set by these bits. These bits range from 250mA to 2.0A. See the CHGCC[4:0] Code Table for more details.	
7:5	R/W	FCHGTIME [2:0]	010	Fast-Charge Timer Duration (t <sub>FC</sub> )  000 = Disable  001 = 4hrs  010 = 5hrs  011 = 6hrs  100 = 7hrs  101 = 8hrs  110 = 9hrs  111 = 16hrs	

### CHGCC[4:0] Code Table

(Current values are shown for a  $47m\Omega$  sense resistor)

0x00 = 0b00000 = 0A	0x10 = 0b10000 = 1.000A
0x01 = 0b00001 = 0.250A	0x11 = 0b10001 = 1.050A
0x02 = 0b00010 = 0.300A	0x12 = 0b10010 = 1.100A
0x03 = 0b00011 = 0.350A	0x13 = 0b10011 = 1.150A
0x04 = 0b00100 = 0.400A	0x14 = 0b10100 = 1.200A
0x05 = 0b00101 = 0.450A	0x15 = 0b10101 = 1.250A
0x06 = 0b00110 = 0.500A	0x16 = 0b10110 = 1.300A
0x07 = 0b00111 = 0.550A	0x17 = 0b10111 = 1.350A
0x08 = 0b01000 = 0.600A	0x18 = 0b11000 = 1.400A
0x09 = 0b01001 = 0.650A	0x19 = 0b11001 = 1.450A
0x0A = 0b01010 = 0.700A	0x1A = 0b11010 = 1.500A
0x0B = 0b01011 = 0.750A	0x1B = 0b11011 = 1.550A
0x0C = 0b01100 = 0.800A	0x1C = 0b11100 = 1.80A
0x0D = 0b01101 = 0.850A	0x1D = 0b11101 = 1.867A
0x0E = 0b01110 = 0.900A	0x1E = 0b11110 = 1.933A
0x0F = 0b01111 = 0.950A	0x1F = 0b11111 = 2.000A

# **Topoff and Temperature Regulation Control Register**

NAME FUNCTION		ADDRESS	TYPE	RESET	
I IOPOFF I		Top off/TEMP Control	0x39	C (Protected with CHGPROT) 0x63	
BIT	MODE	NAME	RESET	DESC	RIPTION
2:0	R/W	ITOPOFF [2:0]	011	Topoff Current Threshold (Topoff timer starts when ICHG reaches this current setting)  0x00 = 0b000 = 50mA  0x01 = 0b001 = 100mA  0x02 = 0b010 = 150mA  0x03 = 0b011 = 200mA  0x04 = 0b100 = 250mA  0x05 = 0b101 = 300mA  0x06 = 0b110 = 350mA  0x0 7 = 0b111 = 400mA	
3	R/W	RESERVED	0	Reserved	
4	R/W	RESERVED	0	Reserved	
7:5	R/W	TOPOFFTIME [2:0]	011	Top Off Timer Setting  0x00 = 0b00 0 = 0min  0x01 = 0b00 1 = 10min  0x02 = 0b010 = 20min  0x03 = 0b011 = 30min  0x04 = 0b100 = 40min  0x05 = 0b101 = 50min  0x06 = 0b110 = 60min  0x07 = 0b111 = Disable (charger never enters DONE state)	

# **Battery Regulation Control Settings Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
В	ATREG	Battery Regulation	0x3A	C (Protected with CHGPROT)	0x16
BIT	MODE	NAME	RESET	DESC	RIPTION
0	R/W	VICHG_GAIN	0	VICHG Gain. I2V gain between charge current and ADC input 0 = 1.41mV/mA 1 = 8.46mV/mA (6x)	
4:1	R/W	MBATREG [3:0]	1011	MBATT Charger Regulation Voltage. See the MBATREG[3:0] Code Table for more details.	
5	R/W	CHGRSTRT	0	Fast Charge Restart Threshold (VMBAT_Ref) 0 = -150mV 1 = -200mV	
7:6	R/W	REGTEMP [1:0]	00	Die Temperature Thermal Regulation Loop Set Point $00 = +105^{\circ}C$ $01 = +90^{\circ}C$ $10 = +120^{\circ}C$ $11 = +75^{\circ}C$	

# MBATREG[3:0] Code Table

0x00 = 0b0000 = 3.55V	0x08 = 0b1000 = 4.05V
0x01 = 0b0001 = 3.70V	0x09 = 0b1001 = 4.10V
0x02 = 0b0010 = 3.75V	0x0A = 0b1010 = 4.15V
0x03 = 0b0011 = 3.80V	0x0B = 0b1011 = 4.20V
0x04 = 0b0100 = 3.85V	0x0C = 0b1100 = 4.25V
0x05 = 0b0101 = 3.90V	0x0D = 0b1101 = 4.30V
0x06 = 0b0110 = 3.95V	0x0E = 0b1110 = 4.35V
0x07 = 0b0111 = 4.00V	0x0F = 0b1111 = 4.40V

# **DC Current Limit Control Settings Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
D	CCRNT	Input Current Limit	0x3B	C (Protected with CHGPROT) 0x0C	
BIT	MODE	NAME	RESET	DESCRIPTION	
5:0	R/W	DCILMT [5:0]	001100	DC Input Current Limit Selection. When the DC-DC converter is and DCILIM_EN = 1, the DC input current limit is set by DCILIM shown in the DCILMT[5:0] Code Table. DCILIM target is always a 95% of programmed value.	
7:6	R/W	RESERVED	00	Reserved	

# DCILMT[5:0] Code Table

0x00 = 0b000000 = 0.100A	0x10 = 0b010000 = 0.600A	0x20 = 0b100000 = 1.000A	0x30 = 0b110000 = 1.400A
0x00 = 0b000001 = 0.100A	0x11 = 0b010001 = 0.625A	0x21 = 0b100001 = 1.025A	0x31 = 0b110001 = 1.425A
0x00 = 0b000010 = 0.100A	0x12 = 0b010010 = 0.650A	0x22 = 0b100010 = 1.050A	0x32 = 0b110010 = 1.450A
0x03 = 0b000011 = 0.275A	0x13 = 0b010011 = 0.675A	0x23 = 0b100011 = 1.075A	0x33 = 0b110011 = 1.475A
0x04 = 0b000100 = 0.300A	0x14 = 0b010100 = 0.700A	0x24 = 0b100100 = 1.100A	0x34 = 0b110100 = 1.500A
0x05 = 0b000101 = 0.325A	0x15 = 0b010101 = 0.725A	0x25 = 0b100101 = 1.125A	0x35 = 0b110101 = 1.709A
0x06 = 0b000110 = 0.350A	0x16 = 0b010110 = 0.750A	0x26 = 0b100110 = 1.150A	0x36 = 0b110110 = 1.750A
0x07 = 0b000111 = 0.375A	0x17 = 0b010111 = 0.775A	0x27 = 0b100111 = 1.175A	0x37 = 0b110111 = 1.792A
0x08 = 0b001000 = 0.400A	0x18 = 0b011000 = 0.800A	0x28 = 0b101000 = 1.200A	0x38 = 0b111000 = 1.834A
0x09 = 0b001001 = 0.425A	0x19 = 0b011001 = 0.825A	0x29 = 0b101001 = 1.225A	0x39 = 0b111001 = 1.875A
0x0A = 0b001010 = 0.450A	0x1A = 0b011010 = 0.850A	0x2A = 0b101010 = 1.250A	0x3A = 0b111010 = 1.917A
0x0B = 0b001011 = 0.475A	0x1B = 0b011011 = 0.875A	0x2B = 0b101011 = 1.275A	0x3B = 0b111011 = 1.959A
0x0C = 0b001100 = 0.500A	0x1C = 0b011100 = 0.900A	0x2C = 0b101100 = 1.300A	0x3C = 0b111100 = 2.000A
0x0D = 0b001101 = 0.525A	0x1D = 0b011101 = 0.925A	0x2D = 0b101101 = 1.325A	0x3D = 0b111101 = 2.042A
0x0E = 0b001110 = 0.550A	0x1E = 0b011110 = 0.950A	0x2E = 0b101110 = 1.350A	0x3E = 0b111110 = 2.084A
0x0F = 0b001111 = 0.575A	0x1F = 0b011111 = 0.975A	0x2F = 0b101111 = 1.375A	0x3F = 0b111111 = No LIMIT

# **AICL Control Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
Al	CLCNTL	AICL	0x3C	C (Protected with CHGPROT)	0x0C
BIT	MODE	NAME	RESET	DESCI	RIPTION
0	R/W	DCMON_DIS	0	DCMON_DIS, disable the monitoring of input voltage by the dynamic input power limited.  0 = AICL enabled  1 = AICL disabled	
4:1	R/W	AICL [3:0]	0110	AICL Detection Voltage Setting. See the AICL [3:0] Code Table for more details.	
5	R/W	AICL_RESET	0	AICL Reset Threshold Below AICL Voltage Setting 0 = 100mV 1 = 200mV	
6	R/W	AICLVTH	0	AICL Threshold Dependency on OVP Threshold 0 = AICL threshold is independent with the OVP threshold (i.e., the AICL threshold does not change with different OVP voltage setting) 1 = AICL threshold is dependent with the OVP threshold (i.e., the AICL threshold changes with different OVP voltage setting accordingly)	
7	R/W	RESERVED	0	Reserved	

# AICL [3:0] Code Table

0x0 = 0b0000 = 3.9V	0x7 = 0b0111 = 4.6V
0x1 = 0b0001 = 4.0V	0x8 = 0b1000 = 4.7V
0x2 = 0b0010 = 4.1V	0x9 = 0b1001 = 4.8V
0x3 = 0b0011 = 4.2V	0x10 = 0b1010 = 4.8V
0x4 = 0b0100 = 4.3V	0x11 = 0b1011 = 4.8V
0x5 = 0b0101 = 4.4V	0x12 = 0b1100 = 4.8V
0x6 = 0b0110 = 4.5V	0x13 = 0b11xx = 4.8V

# **Reverse Boost Control 1 Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
RBO	OST_CTL1	Reverse Boost Control #1	0x3D	D 0x20	
BIT	MODE	NAME	RESET	DESCRIPTION	ON
0	R/W	RBOOSTEN	0	0 = Reverse boost disabled 1 = Reverse boost enabled	
3:1	R/W	RESERVED	000	Reserved	
4	R/W	RBFORCEPWM	0	Force Boost PWM Enable/Disable 0 = Force boost PWM disabled 1 = Force reverse boost to operate in PWM mode for better transient response	
7:5	R/W	BSTSOFTSLEW RATE [2:0]	001	transient response  Soft Slew Rate Control 000 = Bypass mode 001 = 1 code (25mV) each T100K*1 period 010 = 1 code (25mV) each T100K*2 period 011 = 1 code (25mV) each T100k*4 period 100 = 1 code (25mV) each T100k*8 period 101 = 1 code (25mV) each T100k*16 period 110 = 1 code (25mV) each T100k*32 period 111 = 1 code (25mV) each T100k*64 period	

# Companion PMIC for Smartphone and Tablet

# **System Control Register**

ı	NAME	FUNCTION	ADDRESS	TYPE	RESET
СН	GCNTL2	SYS Control	0x3E	C (Protected with CHGPROT) 0x36	
BIT	MODE	NAME	RESET	DESCRIP	TION
2:0	R/W	VSYSREG [2:0]	110	Minimum V <sub>SYS</sub> Regulation Voltage. <i>Table</i> for more details.	See the VSYSREG [2:0] Code
3	R/W	QBATEN	0	External pMOSFET Control. This bit allows the user to short SYS and BAT through SW. Under default conditions, QBAT switch is controlled through hardware state diagram during pre-charge to fast-charge conditions and in DONE state. However, this bit could provide flexibility to customers who intend to do SW charging instead of smart battery charging.  0 = Off 1 = On	
4	R/W	CEN	1	Charging Control. This bit allows the user to control when to enable charging.  0 = Off 1 = On	
6:5	R/W	PREQCUR [1:0]	01	Prequal Current: 00 = 100mA 01 = 200mA 10 = 300mA 11 = 400mA	
7	R/W	DCILIM_EN	0	Input Current Limit Control Enables the DC input current limit register to be controlled.  0 = The input current limit is controlled through USB_HICURRENT register bit.  1 = The input current limit is controlled through DCILMT [5:0] register bits.	

# VSYSREG [2:0] Code Table

0x0 = 0b000 = 3.0V
0x1 = 0b001 = 3.1V
0x2 = 0b010 = 3.2V
0x3 = 0b011 = 3.3V
0x4 = 0b100 = 3.4V
0x5 = 0b101 = 3.5V
0x6 = 0b110 = 3.6V
0x7 = 0b111 = 4.0V

# **Battery Insertion/Removal Register**

ı	NAME	FUNCTION	ADDRESS	TYPE	RESET
В	ATDET	Battery Detection	0x3F	0	0x6E
BIT	MODE	NAME	RESET	DESCRI	PTION
0	R/W	BAT_SIM_DEB	0	0 = The SIM card battery removal signal (BAT_REMOVED_SIM) is derived from a debounced timer that uses 3 cycle of 100kHz oscillator. The debounce time is between 30μs and 40μs. 1 = The SIM card battery removal signal (BAT_REMOVED_SIM) is the same signal as BAT_REMOVED which is programmed by TDEB_BATREM [4:0].	
5:1	R/W	TDEB_BATREM [4:0]	10111	Battery Removal Debounce Timer Count (BAT_REMOVED).  This timer is driven from divide by 1 tap of the 100kHz oscillator.  t <sub>MIN</sub> = COUNT x 1/100kHz  t <sub>MAX</sub> = t <sub>MIN</sub> +1/100kHz	
6	R/W	BATDETENB	1	Battery Detection Enable/Disable Bit 0 = Battery detection enable 1 = Battery detection disable	
7	R/W	STRONGPUENB	0	Battery Detection Strong Pullup Enable/Disable Bit 0 = Pullup enable 1 = Pullup disable	

# Companion PMIC for Smartphone and Tablet

# **USB Charger Control Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
USI	BCHGCTL	USB Charger Control	0x40	С	0x00
BIT	MODE	NAME	RESET	DESCR	IPTION
0	R/W	LOW_BAT	0	Low Battery Output  0 = The battery voltage level, V <sub>MBATT</sub> > V <sub>PQUTH</sub> and V <sub>DC</sub> or VW is valid.  1 = The battery voltage level, V <sub>MBATT</sub> < V <sub>PQUTH</sub> and V <sub>DC</sub> is valid and VWC is invalid.	
1	R/W	RESERVED	0	Reserved	
2	R/W	USB_SUSPEND	0	USB Suspend Input 0 = Set DC input current limit based on USB_HICURRENT, DCILMT [5:0], and DCILM_EN configuration bits. 1 = Disable the DC input	
3	R/W	USB_HICURRENT	0	USB_HICURRENT Input. USB_HICURRENT controls the input current limit of the main-battery charger's DC input when DCILMT_EN = 0. When DCILMT_EN = 1, the DC input current limit is controlled by DCILMT [5:0].  0 = Set the DC input current limit to 100mA 1 = Set the DC input current limit to 500mA	
4	R/W	RESERVED	0	Reserved	
5	R/W	RESERVED	0	Reserved	
6	R/W	RESERVED	0	Reserved	
7	R/W	DISTIMER	0	Charging Timer Control 0 = Enable Timer 0 1 = Disable Timer 0	

# **Maximum Charge Termination Voltage Register**

	NAME	FUNCTION	ADDRESS	TYPE	RESET
MBA	TREGMAX	Max Charge Voltage	0x41 O 0x0F		0x0F
BIT	MODE	NAME	RESET	DESCRIPTION	
3:0	R/W	MBATMAX [3:0]	1111	Maximum Charge Termination Voltage. The effective termination charge voltage is clamped by MBATMAX [3:0].  MBATMAX follows the same code table as MBATREG	
7:4	R/W	RESERVED	0000	Reserved	

# **Maximum Charge Current Register**

	NAME FUNCTION ADDRESS TYPE		RESET			
СН	CHGCCMAX Max Charge 0x42 O		0x1F			
BIT	MODE	NAME	RESET	DESCRIF	PTION	
4:0	R/W	CHGCCMAX [4:0]	11111	Maximum Charge Current. The effective charge current is clamped by CHGCCMAX [4:0].		
7:5	R/W	RESERVED	000	Reserved		

# **BYP Target Output Voltage in Boost Mode Register**

ı	NAME FUNCTION		ADDRESS	TYPE	RESET	
RBOOST_CTL2		BYP Target Output Voltage in Boost Mode	0x43	D	0x00	
BIT	MODE	NAME	RESET	DESCRIPTION		
6:0	R/W	VBYPSET	0x00 (3V)	Bypass Target Output Voltage in Boost Mode. 3V (0x00) to 5.8V (0x70) in 0.025V steps. This setting is compared to the setting coming from the camera flash controller's adaptive circuit and the boost target voltage is the higher of the two.		
7	R/W	RESERVED	0	Reserved		

# **VBYPSET [6:0] Setting**

(Note the presence of redundant codes)

0x00 = 3.000V	0x10 = 3.400V	0x20 = 3.800V	0x30 = 4.200V	0x40 = 4.600V	0x50 = 5.000V	0x60 = 5.400V	0x70 = 5.800V
0x01 = 3.025V	0x11 = 3.425V	0x21 = 3.825V	0x31 = 4.225V	0x41 = 4.625V	0x51 = 5.025V	0x61 = 5.425V	0x71 = 5.800V
0x02 = 3.050V	0x12 = 3.450V	0x22 = 3.850V	0x32 = 4.250V	0x42 = 4.650V	0x52 = 5.050V	0x62 = 5.450V	0x72 = 5.800V
0x03 = 3.075V	0x13 = 3.475V	0x23 = 3.875V	0x33 = 4.275V	0x43 = 4.675V	0x53 = 5.075V	0x63 = 5.475V	0x73 = 5.800V
0x04 = 3.100V	0x14 = 3.500V	0x24 = 3.900V	0x34 = 4.300V	0x44 = 4.700V	0x54 = 5.100V	0x64 = 5.500V	0x74 = 5.800V
0x05 = 3.125V	0x15 = 3.525V	0x25 = 3.925V	0x35 = 4.325V	0x45 = 4.725V	0x55 = 5.125V	0x65 = 5.525V	0x75 = 5.800V
0x06 = 3.150V	0x16 = 3.550V	0x26 = 3.950V	0x36 = 4.350V	0x46 = 4.750V	0x56 = 5.150V	0x66 = 5.550V	0x76 = 5.800V
0x07 = 3.175V	0x17 = 3.575V	0x27 = 3.975V	0x37 = 4.375V	0x47 = 4.775V	0x57 = 5.175V	0x67 = 5.575V	0x77 = 5.800V
0x08 = 3.200V	0x18 = 3.600V	0x28 = 4.000V	0x38 = 4.400V	0x48 = 4.800V	0x58 = 5.200V	0x68 = 5.600V	0x78 = 5.800V
0x09 = 3.225V	0x19 = 3.625V	0x29 = 4.025V	0x39 = 4.425V	0x49 = 4.825V	0x59 = 5.225V	0x69 = 5.625V	0x79 = 5.800V
0x0A = 3.250V	0x1A = 3.650V	0x2A = 4.050V	0x3A = 4.450V	0x4A = 4.850V	0x5A = 5.250V	0x6A = 5.650V	0x7A = 5.800V
0x0B = 3.275V	0x1B = 3.675V	0x2B = 4.075V	0x3B = 4.475V	0x4B = 4.875V	0x5B = 5.275V	0x6B = 5.675V	0x7B = 5.800V
0x0C = 3.300V	0x1C = 3.700V	0x2C = 4.100V	0x3C = 4.500V	0x4C = 4.900V	0x5C = 5.300V	0x6C = 5.700V	0x7C = 5.800V
0x0D = 3.325V	0x1D = 3.725V	0x2D = 4.125V	0x3D = 4.525V	0x4D = 4.925V	0x5D = 5.325V	0x6D = 5.725V	0x7D = 5.800V
0x0E = 3.350V	0x1E = 3.750V	0x2E = 4.150V	0x3E = 4.550V	0x4E = 4.950V	0x5E = 5.350V	0x6E = 5.750V	0x7E = 5.800V
0x0F = 3.375V	0x1F = 3.775V	0x2F = 4.175V	0x3F = 4.575V	0x4F = 4.975V	0x5F = 5.375V	0x6F = 5.775V	0x7F = 5.800V

# **Charger Interrupt 2 Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET	
СН	IGINT2	Charger Watchdog Timer Interrupt	0x44	O 0x00		
BIT	MODE	NAME	RESET	DESCRIPTIO	N	
0	R/C	CHG_WDT_WRN_I	0	Charger Watchdog Timer Warning Interrupt 0 = The charger watchdog timer has not come within 2s of expiring since the last time this bit was read. 1 = The charge watchdog timer has come within 2s of expiring since the last time this bit was read.		
3:1	R/C	RESERVED	0	Reserved		
4	R/C	CHG_WDT_I	0	Charger Watchdog Timer Expire Interrupt 0 = The charger watchdog timer is not expired since the last time this bit was read. 1 = The charger watchdog timer is expired since the last time this bi was read.		
6:5	R/C	RESERVED	0	Reserved		
7	R/C	DC_V_I	0	DC_V Interrupt 0 = DC_V voltage is equal or less than 5.9V 1 = DC_V voltage is higher than 5.9V		

# **Charger Watchdog Timer Interrupt Masks Register**

1	NAME	FUNCTION	ADDRESS	TYPE RESET		
CHGINTMASK2 Charger Watchdog Timer Interrupt Mask 0x45		0	0x00			
BIT	MODE	NAME	RESET	DESCRI	PTION	
0	R/W	CHG_WDT_ WRN_M	0	Charger Watchdog Timer Warning Mask 0 = Unmask 1 = Mask		
3:1	R/W	RESERVED	0	Reserved		
4	R/W	CHG_WDT_M	0	Charger Watchdog Timer Expire M 0 = Unmask 1 = Mask	lask	
6:5	R/W	RESERVED	0	Reserved		
7	R/W	DC_V_M	0	DC_V Interrupt Mask 0 = Unmask 1 = Mask		

# **Charger Watchdog Timer Clear Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET
CHG_WDTC		Charger Watchdog Timer Clear	0x46	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
1:0	R/W	CHG_WDTC [1:0]	00	Charger Watchdog Timer Clear. Writing 0b01 to these bits clears the watchdog timer. These bits automatically reset to 0b00 after they are written to 0b01.  0b00 = The system watchdog timer is not cleared.  0b01 = The system watchdog timer is not cleared.  0b10 = The system watchdog timer is not cleared.  0b11 = The system watchdog timer is not cleared.	
7:2	R/W	RESERVED	0	Reserved	

# **Charger Watchdog Timer Control Register**

	NAME	FUNCTION	ADDRESS	TYPE RESET		
CHG <sub>.</sub>	_WDT_CTL	Charger Watchdog Timer Control	0x47	O 0x40		
BIT	MODE	NAME	RESET	DESCRIPTION		
0	R/W	CHG_WDT_EN	0	Charger Watchdog Timer Enable Bit 0 = Disabled 1 = Enabled		
5:1	R/W	RESERVED	0	Reserved		
7:6	R/W	CHG_WDT [1:0]	01	Reserved  Charger Watchdog Timer Period 0b00 = 16s 0b01 = 32s 0b10 = 64s 0b11 = 128s The charger watchdog timer period may be changed at any time, however the new value is not implemented until the watchdog timer is cleared (CHG_WDTC [1:0] = 0b01). It is recommended that software clears the timer shortly after any watchdog timer period change.		

# **Charger Watchdog Timer Status Register**

	NAME FUNCTIO		ADDRESS	TYPE	RESET
CHG_WDT_DTLS		Charger Watchdog Timer Status	0x48	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
0	R	CHG_WDT_WRN _STAT	0	Charger Watchdog Warning 0 = The charger watchdog timer has not cor 1 = The charger watchdog timer has come was	
3:1	R	RESERVED	0	Reserved	
4	R	CHG_WDT_ STAT	0	Charger Watchdog Timer 0 = Timer not expires 1 = Timer expires	
7:5	R	RESERVED	0	Reserved	

# **SAFEOUT LDO Control Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET	
SAFE	EOUTCTL	SAFEOUT Linear Regulator Control	0x4B	0	0x51	
BIT	MODE	NAME	RESET	DESCRIPTION		
1:0	R/W	SAFEOUT [1:0]	01	SAFEOUT Output Voltage 00 = 4.85V 01 = 4.90V (default) 10 = 4.95V 11 = 3.3V		
3:2	R/W	RESERVED	00	Reserved		
4	R/W	ACTDISSAFEO1	1	0 = No active discharge 1 = Active discharge		
5	R/W	RESERVED	0	Reserved		
6	R/W	SAFEOUT_EN	1	SAFEOUTLDO Enable Bit 0 = Disable SAFEOUT 1 = Enable SAFEOUT		
7	R/W	RESERVED	0	Reserved		

# **Flash Register Details**

# **FLED1 Flash Current Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET	
IFLASH1		FLED1 Flash Current Setting	0x00	0	0x00	
BIT	MODE	NAME	RESET	DESCRIPTION		
4:0	R/W	FLASH1_I	000000	Sets the FLED1 Current in FLASH Mode. 23.436mA–750mA in 5-bits, 32 steps, 23.4	•	
5	R/W	RESERVED	0	Reserved		
6	R/W	RESERVED	0	Reserved		
7	R/W	RESERVED	0	Reserved		

### **FLED2 Flash Current Register**

N	IAME	FUNCTION	ADDRESS	TYPE RESE	
IFLASH2 FLED2 Flash Ox01		O 0x00			
BIT	MODE	NAME	RESET	DESCRIPTION	
4:0	R/W	FLASH2_I	00000	Sets the FLED2 Current in FLASH Mode. 723.436mA-750mA in 5-bits, 32 steps, 23.436mA-750mA in 5-bits, 32 steps, 32 st	
5	R/W	RESERVED	0	Reserved	
6	R/W	RESERVED	0	Reserved	
7	R/W	RESERVED	0	Reserved	

# IFlash\_1/IFLASH\_2[4:0] Value Table

IFIASH_x [4:0]	FLEDxFlash Current (mA)						
0x00	23.436	80x0	210.924	0x10	398.412	0x18	585.9
0x01	46.872	0x09	234.36	0x11	421.848	0x19	609.336
0x02	70.308	0x0A	257.796	0x12	445.284	0x1A	632.772
0x03	93.744	0x0B	281.232	0x13	468.72	0x1B	656.208
0x04	117.18	0x0C	304.668	0x14	492.156	0x1C	679.644
0x05	140.616	0x0D	328.104	0x15	515.592	0x1D	703.08
0x06	164.052	0x0E	351.54	0x16	539.028	0x1E	726.516
0x07	187.488	0x0F	374.976	0x17	562.464	0x1F	749.952

# **FLED Torch Currents Register**

NAME		FUNCTION	ADDRESS	TYPE	RESET
ITORCH		FLED Torch Current Settings	0x02	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
3:0	R/W	TORCH_IOUT	0000	Sets FLED1 and FLED2 Total Current in TORCH Mode Adjustable from 23.436mA to 375mA in 4-bits, 16 steps, 23.436mA/step (11.72mA to 187.5mA per channel).	
7:4	R/W	RESERVED	0000	Reserved	

### Torch\_IOUT[3:0] Value Table

Torch_IOUT [3:0]	FLEDxTorch Current (mA)	Torch_IOUT [3:0]	FLEDxTorch Current (mA)	Torch_IOUT [3:0]	FLEDxTorch Current (mA)	Torch_IOUT [3:0]	FLEDxTorch Current (mA)
0x00	23.436	0x04	117.18	0x08	210.924	0x0C	304.668
0x01	46.872	0x05	140.616	0x09	234.36	0x0D	328.104
0x02	70.308	0x06	164.052	0x0A	257.796	0x0E	351.54
0x03	93.744	0x07	187.488	0x0B	281.232	0x0F	374.976

# **Torch Timer Register**

NAME		FUNCTION	ADDRESS	TYPE	RESET	
TORCH_TMR		Torch Timer Settings	0x03	0	0x00	
BIT	MODE	NAME	RESET	DESCRIPTION		
3:0	R/W	TORCH_TMR_DUR	0000	Torch Safety Timer setting  0x00 = 262ms  0x01 = 524ms  0x02 = 786ms  0x03 = 1.048s  0x04 = 1.572s  0x05 = 2.096s  0x06 = 2.62s  0x07 = 3.144s  0x08 = 4.193s  0x09 = 5.242s  0x0A = 6.291s  0x0B = 7.34s  0x0C = 9.437s  0x0D = 11.534s  0x0F = 15.728s		
4	R/W	RESERVED	0	Reserved		
5	R/W	RESERVED	0	Reserved		
6	R/W	DIS_TORCH_TMR	0	Torch Safety Timer Enable Control 0 = Torch safety timer enabled. 1 = Torch safety timer disabled.		
7	R/W	TORCH_TMR_MODE	0	Torch Mode Timer Control 0 = ONE SHOT 1 = Run for MAX timer		

# Flash Timer Register

NAME		FUNCTION	ADDRESS	TYPE	RESET	
FLAS	SH_TMR	Flash Timer Settings	0x04	0	0x00	
BIT	MODE	NAME	RESET	DESCRIPTION		
3:0	R/W	FLASH_TMR_DUR	0000	Flash Safety Timer Setting 62.5ms to 1000ms adjustable in 62.5ms steps.		
4	R/W	RESERVED	0	Reserved		
5	R/W	RESERVED	0	Reserved		
6	R/W	RESERVED	0	Reserved		
7	R/W	FLASH_TMR_MODE	0	FLASH Mode Timer Control 0 = ONE SHOT 1 = Run for MAX timer		

## **FLED Enable Settings Register**

N.	AME	FUNCTION	ADDRESS	TYPE RESET	
FLA	SH_EN	FLED Enable Settings	0x05	O 0x00	
BIT	MODE	NAME	RESET	DESCRIPTION	
1:0	R/W	TORCH_ FLED2_EN	00	Enable/Disable Control for Torch Mode on FLED2  0x00 = Torch OFF  0x01 = Torch triggered by FLASHEN  0x02 = Torch triggered by TORCHEN  0x03 = Torch triggered through serial interface	
3:2	R/W	TORCH_FLED1_EN	00	Enable/Disable Control for Torch Mode on FLED1  0x00 = Torch OFF  0x01 = Torch triggered by FLASHEN  0x02 = Torch triggered by TORCHEN  0x03 = Torch triggered through serial interface	
5:4	R/W	FLASH_ FLED2_EN	00	Enable/Disable Control for Flash Mode on FLED2  00 = Flash OFF  01 = Flash triggered by FLASHEN  10 = Torch triggered by TORCHEN  11 = Flash triggered through serial interface	
7:6	R/W	FLASH_FLED1_EN	00	Enable/Disable Control for Flash Mode on FLED1 00 = Flash OFF 01 = Flash triggered by FLASHEN 10 = Torch triggered by TORCHEN 11 = Flash triggered through serial interface	

**Note:** Flash has higher priority always over Torch. If user tried to simultaneously start FLASH and TORCH, the FLED will Flash to completion, then initiate Torch.

#### **MAXFLASH Voltage Settings Register**

N	АМЕ	FUNCTION	ADDRESS	TYPE RESET	
MAX_	FLASH1	MAXFLASH Voltage Settings	0x06	O 0x00	
BIT	MODE	NAME	RESET	DESCR	IPTION
1:0	R/W	MAX_FLASH_HYS	00	Low Battery Detection Hysteresis  0x00 = 100mV  0x01 = 200mV  0x02 = 300mV  0x03 = Hysteresis disabled. Flash current is only reduced.	
6:2	R/W	MAX_FLASH_TH	00000	MAXFLASH Function, Low Battery Detection Threshold 0x00 = 0x1F = 2.4V to 3.4V adjustable in 33mV steps 0x00 = 2.4V 0x1E = 0x1F = 3.4V	
7	R/W	MAX_FL_EN	0	MAXFLASH Function Enable/Disable 0 = MAXFLASH disabled 1 = MAXFLASH enabled	

## **MAXFLASH Timer Settings Register**

N.	NAME FUNCTION		ADDRESS	TYPE	RESET
MAX_FLASH2		MAXFLASH Timer Settings	0x07	O 0x00	
BIT	MODE	NAME	RESET	DESCRIPTION	
2:0	R/W	LB_TMR_F	000	Low Battery Mask Timer for Falling Edge of Battery Adjustable from 256µs to 2048µs in 256µs steps.	
5:3	R/W	LB_TMR_R	000	Low Battery Mask Timer for Rising Edge of Battery Adjustable from 256µs to 2048µs in 256µs steps.	
6	R/W	RESERVED	0	Reserved	
7	R/W	RESERVED	0	Reserved	

# **MAXFLASH FLED1 Status Register**

NAME FUNCTION		FUNCTION	ADDRESS	TYPE	RESET
MAX_FLASH3		MAXFLASH Status – FLED1	0x08	O 0x00	
BIT	MODE	NAME	RESET	DESCRIPTION	ON
5:0	R/W	FLED1_MIN_OUT	000000	Minimum Output Current During a MA Status of the current level for a MAXFI In flash mode, this number is lower tha torch mode, it is lower than TORCH_IC Reading from 11.72mA-750mA in 11.7	LASH event on FLED1. an FLASH_IOUT1, in DUT1.
6	R/W	RESERVED	0	Reserved	
7	R/W	FLED1_MIN_MODE	0	MAX_FLASH Triggered on FLED1, Triggered In 0 = Torch mode 1 = Flash mode	

## **MAXFLASH FLED2 Status Register**

N	NAME	FUNCTION	ADDRESS	TYPE	RESET
MAX_FLASH4		MAXFLASH Status – FLED2	0x09	O 0x00	
BIT	MODE	NAME	RESET	DESCRIPT	ION
5:0	R/W	FLED2_MIN_OUT	000000	Minimum output current during a MA status of the current level for a MAXI flash mode, this number is lower than mode, it is lower than TORCH_IOUT Reading from 11.72mA-750mA in 11	FLASH event on FLED2. In n FLASH_IOUT2, in torch 22.
6	R/W	RESERVED	0	Reserved	
7	R/W	FLED2_MIN_MODE	0	MAX_FLASH Triggered on FLED2, Triggered In 0 = Torch mode 1 = Flash mode	

## **Boost Control Mode Register**

N.	AME	FUNCTION	ADDRESS	TYPE RESET	
VOU.	T_CNTL	Boost Control Settings	0x0A	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	ON
2:0	R/W	BOOST_FLASH_MODE	000	Mode of Operation for the Flash 000 = Flash is OFF 001 = FLED1 in adaptive mode 010 = FLED2 in adaptive mode 011 = FLED1 and FLED2 in adaptive mode 100 = Fixed Mode 101–111 = Reserved	
3	R/W	RESERVED	0	Reserved	
4	R/W	RESERVED	0	Reserved	
5	R/W	RESERVED	0	Reserved	
6	R/W	RESERVED	0	Reserved	
7	R/W	FLEDNUM	0	0 = Only 1 FLED source is used. Current for FLED powered from boost is limited to 1A. 1 = Both FLED1 and FLED2 are used. Current in FLED powered from boost is limited to 625mA/FLED source. This bit must be enabled only when both FLED sources are used.	

## **Boost Voltage Settings Register**

N.	AME	FUNCTION	ADDRESS	TYPE RESET	
VOUT	_FLASH	Boost Voltage Settings	0x0B	O 0x00	
BIT	MODE	NAME	RESET	DESCRIPTION	ON
6:0	R/W	BOOST_VOUT_FLASH	0000000	3.3V to 5.5V adjustable in 25mV step: If Adaptive mode is selected, this register (as long as BYP voltage in this register the charger and reverse boost is ON)  See the BOOST_VOUT_FLASH [6:0] details.  Note the presence of redundant code	ster contents are ignored. represents the BYP voltage er is > BYP voltage set in .  Setting table for more
7	R/W	RESERVED	0	Reserved	

## BOOST\_VOUT\_FLASH [6:0] Setting

(Note the presence of redundant codes)

0x00 = 3.300V	0x10 = 3.400V	0x20 = 3.800V	0x30 = 4.200V	0x40 = 4.600V	0x50 = 5.000V	0x60 = 5.400V	0x70 = 5.500V
0x01 = 3.300V	0x11 = 3.425V	0x21 = 3.825V	0x31 = 4.225V	0x41 = 4.625V	0x51 = 5.025V	0x61 = 5.425V	0x71 = 5.500V
0x02 = 3.300V	0x12 = 3.450V	0x22 = 3.850V	0x32 = 4.250V	0x42 = 4.650V	0x52 = 5.050V	0x62 = 5.450V	0x72 = 5.500V
0x03 = 3.300V	0x13 = 3.475V	0x23 = 3.875V	0x33 = 4.275V	0x43 = 4.675V	0x53 = 5.075V	0x63 = 5.475V	0x73 = 5.500V
0x04 = 3.300V	0x14 = 3.500V	0x24 = 3.900V	0x34 = 4.300V	0x44 = 4.700V	0x54 = 5.100V	0x64 = 5.500V	0x74 = 5.500V
0x05 = 3.300V	0x15 = 3.525V	0x25 = 3.925V	0x35 = 4.325V	0x45 = 4.725V	0x55 = 5.125V	0x65 = 5.500V	0x75 = 5.500V
0x06 = 3.300V	0x16 = 3.550V	0x26 = 3.950V	0x36 = 4.350V	0x46 = 4.750V	0x56 = 5.150V	0x66 = 5.500V	0x76 = 5.500V
0x07 = 3.300V	0x17 = 3.575V	0x27 = 3.975V	0x37 = 4.375V	0x47 = 4.775V	0x57 = 5.175V	0x67 = 5.500V	0x77 = 5.500V
0x08 = 3.300V	0x18 = 3.600V	0x28 = 4.000V	0x38 = 4.400V	0x48 = 4.800V	0x58 = 5.200V	0x68 = 5.500V	0x78 = 5.500V
0x09 = 3.300V	0x19 = 3.625V	0x29 = 4.025V	0x39 = 4.425V	0x49 = 4.825V	0x59 = 5.225V	0x69 = 5.500V	0x79 = 5.500V
0x0A = 3.300V	0x1A = 3.650V	0x2A = 4.050V	0x3A = 4.450V	0x4A = 4.850V	0x5A = 5.250V	0x6A = 5.500V	0x7A = 5.500V
0x0B = 3.300V	0x1B = 3.675V	0x2B = 4.075V	0x3B = 4.475V	0x4B = 4.875V	0x5B = 5.275V	0x6B = 5.500V	0x7B = 5.500V
0x0C = 3.300V	0x1C = 3.700V	0x2C = 4.100V	0x3C = 4.500V	0x4C = 4.900V	0x5C = 5.300V	0x6C = 5.500V	0x7C = 5.500V
0x0D = 3.325V	0x1D = 3.725V	0x2D = 4.125V	0x3D = 4.525V	0x4D = 4.925V	0x5D = 5.325V	0x6D = 5.500V	0x7D = 5.500V
0x0E = 3.350V	0x1E = 3.750V	0x2E = 4.150V	0x3E = 4.550V	0x4E = 4.950V	0x5E = 5.350V	0x6E = 5.500V	0x7E = 5.500V
0x0F = 3.375V	0x1F = 3.775V	0x2F = 4.175V	0x3F = 4.575V	0x4F = 4.975V	0x5F = 5.375V	0x6F = 5.500V	0x7F = 5.500V

#### Flash Interrupts Register

N.	AME	FUNCTION	ADDRESS	TYPE RESET	
FLA	SH_INT	Flash Interrupts	0x0E	S1	0x00
BIT	MODE	NAME	RESET	DESCRIPT	ION
0	R/C	FLED2_OPEN	0	Interrupt indicating that an FLED1 open has been detected.  0 = FLED2 open not detected  1 = FLED2 open occurred	
1	R/C	FLED2_SHORT	0	Interrupt indicating that an FLED2 short has been detected.  0 = FLED2 short not detected  1 = FLED2 short occurred	
2	R/C	FLED1_OPEN	0	Interrupt indicating that an FLED1 open has been detected.  0 = FLED1 open not detected  1 = FLED1 open occurred	
3	R/C	FLED1_SHORT	0	Interrupt indicating that an FLED1 sho 0 = FLED1 short not detected 1 = FLED1 short occurred	ort has been detected.
4	R/C	MAX_FLASH	0	MAXFLASH Interrupt 0 = MAXFLASH not triggered 1 = MAXFLASH triggered during a flash event	
5	R/C	FLED_FAIL	0	Interrupt indicating the FLED current is not maintained.  0 = FLED current was maintained for flash/torch period.  1 = FLED current was not maintained for flash/torch period.	
6	R/C	RESERVED	0	Reserved	
7	R/C	RESERVED	0	Reserved	

## Flash Interrupt Masks Register

N.	AME	FUNCTION	ADDRESS	TYPE	RESET
FLASH_	INT_MASK	Flash Interrupt Masks	0x0F	S1 0xFF	
BIT	MODE	NAME	RESET	DESCRIPTION	N
0	R/W	FLED2_OPEN_m	1	Mask for FLED2 Open Interrupt 0 = Interrupt is not masked 1 = Interrupt is masked	
1	R/W	FLED2_SHORT_m	1	Mask for FLED2 Short Interrupt 0 = Interrupt is not masked 1 = Interrupt is masked	
2	R/W	FLED1_OPEN_m	1	Mask for FLED1 Open Interrupt 0 = Interrupt is not masked 1 = Interrupt is masked	
3	R/W	FLED1_SHORT_m	1	Mask for FLED1 Short Interrupt 0 = Interrupt is not masked 1 = Interrupt is masked	
4	R/W	MAX_FLASH_m	1	MAXFLASH Interrupt Mask 0 = MAXFLASH_IRQ interrupt is maske 1 = MAXFLASH_IRQ interrupt is not ma	
5	R/W	FLED_FAIL_m	1	Mask for FLED Current is Not Maintaine 0 = Interrupt is masked 1 = Interrupt is not masked	ed
6	R/W	RESERVED	1	Reserved	
7	R/W	RESERVED	1	Reserved	

## FLASH\_STATUS Register

	_	•			
N	AME	FUNCTION	ADDRESS	TYPE	RESET
FLASH	_STATUS	Flash Interrupt Masks	0x10	S1	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
0	R	RESERVED	0	Reserved	
1	R	RESERVED	0	Reserved	
2	R	TORCH_ON_STAT	0	Torch Mode in Progress 0 = No torch mode in progress. 1 = Torch mode in progress.	
3	R	FLASH_ON_STAT	0	Flash Mode in Progress Interrupt 0 = No flash mode in progress. 1 = Flash mode in progress.	
4	R	RESERVED	0	Reserved	
5	R	RESERVED	0	Reserved	
6	R	RESERVED	0	Reserved	
7	R	RESERVED	0	Reserved	

# **WLED Backlight Driver Register Details**

## **WLED Driver Control Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET
WLED	BSTCNTL1	Control Register	0x98	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
0	R/W	RESERVED	0	Reserved	
1	R/W	WLEDOVP	0	WLED Boost OVP Threshold Setting 0 = 28V (max) 1 = 35V (max)	3
3:2	R/W	WLEDFOSC	00	WLEDBST Converter Switching Frequency Select 0x00 = WLEDBST converter switches at 733kHz. 0x01 = WLEDBST converter switches at 1.1MHz. 0x02 = WLEDBST converter switches at 1.47MHz. 0x03 = WLEDBST converter switches at 2.2MHz.	
4	R/W	WLEDPWM2EN	0	Content-Adaptive Brightness Control Enable for Current Source 2 0 = WLEDPWM signal does not affect current source 2 output current. 1 = WLEDPWM signal linearly decreases current source 2 output current with duty cycle.	
5	R/W	WLEDPWM1EN	0	Content-Adaptive Brightness Contro 0 = WLEDPWM signal does not affe current. 1 = WLEDPWM signal linearly decre current with duty cycle.	ct current source 1 output
6	R/W	WLED2EN	0	Current Source 2 Enable 0 = Current source 2 is disabled. 1 = Current source 2 is enabled. Enabling any current source automatically enables the boost converter as well.	
7	R/W	WLED1EN	0	Current Source 1 Enable 0 = Current source 1 is disabled. 1 = Current source 1 is enabled. Enabling any current source automatically enables the boost converter as well.	

## **WLED Currents Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET
IV	VLED	WLED Current	0x99	0	0x00
BIT	MODE	NAME	RESET	DESCRIPTION	
7:0	R/W	IWLED	00000000	Sets the WLED current in both strings from 0mA to 24.9024mA in 97.6563µA.	

## WLED Current [7:0]

0x00 = 0.0000mA	0x20 = 3.1250mA	0x40 = 6.2500mA	0x60 = 9.3750mA
0x01 = 0.0977mA	0x21 = 3.2227mA	0x41 = 6.3477mA	0x61 = 9.4727mA
0x02 = 0.1953mA	0x22 = 3.3203mA	0x42 = 6.4453mA	0x62 = 9.5703mA
0x03 = 0.2930mA	0x23 = 3.4180mA	0x43 = 6.5430mA	0x63 = 9.6680mA
0x04 = 0.3906mA	0x24 = 3.5156mA	0x44 = 6.6406mA	0x64 = 9.7656mA
0x05 = 0.4883mA	0x25 = 3.6133mA	0x45 = 6.7383mA	0x65 = 9.8633mA
0x06 = 0.5859mA	0x26 = 3.7109mA	0x46 = 6.8359mA	0x66 = 9.9609mA
0x07 = 0.6836mA	0x27 = 3.8086mA	0x47 = 6.9336mA	0x67 = 10.0586mA
0x08 = 0.7813mA	0x28 = 3.9063mA	0x48 = 7.0313mA	0x68 = 10.1563mA
0x09 = 0.8789mA	0x29 = 4.0039mA	0x49 = 7.1289mA	0x69 = 10.2539mA
0xA = 0.9766mA	0x2A = 4.1016mA	0x4A = 7.2266mA	0x6A = 10.3516mA
0xB = 1.0742mA	0x2B = 4.1992mA	0x4B = 7.3242mA	0x6B = 10.4492mA
0xC = 1.1719mA	0x2C = 4.2969mA	0x4C = 7.4219mA	0x6C = 10.5469mA
0xD = 1.2695mA	0x2D = 4.3945mA	0x4D = 7.5195mA	0x6D = 10.6445mA
0xE = 1.3672mA	0x2E = 4.4922mA	0x4E = 7.6172mA	0x6E = 10.7422mA
0xF = 1.4648mA	0x2F = 4.5898mA	0x4F = 7.7148mA	0x6F = 10.8398mA
0x10 = 1.5625mA	0x30 = 4.6875mA	0x50 = 7.8125mA	0x70 = 10.9375mA
0x11 = 1.6602mA	0x31 = 4.7852mA	0x51 = 7.9102mA	0x71 = 11.0352mA
0x12 = 1.7578mA	0x32 = 4.8828mA	0x52 = 8.0078mA	0x72 = 11.1328mA
0x13 = 1.8555mA	0x33 = 4.9805mA	0x53 = 8.1055mA	0x73 = 11.2305mA
0x14 = 1.9531mA	0x34 = 5.0781mA	0x54 = 8.2031mA	0x74 = 11.3281mA
0x15 = 2.0508mA	0x35 = 5.1758mA	0x55 = 8.3008mA	0x75 = 11.4258mA
0x16 = 2.1484mA	0x36 = 5.2734mA	0x56 = 8.3984mA	0x76 = 11.5234mA
0x17 = 2.2461mA	0x37 = 5.3711mA	0x57 = 8.4961mA	0x77 = 11.6211mA
0x18 = 2.3438mA	0x38 = 5.4688mA	0x58 = 8.5938mA	0x78 = 11.7188mA
0x19 = 2.4414mA	0x39 = 5.5664mA	0x59 = 8.6914mA	0x79 = 11.8164mA
0x1A = 2.5391mA	0x3A = 5.6641mA	0x5A = 8.7891mA	0x7A = 11.9141mA
0x1B = 2.6367mA	0x3B = 5.7617mA	0x5B = 8.8867mA	0x7B = 12.0117mA

## WLED Current [7:0] (continued)

	T		
0x1C = 2.7344mA	0x3C = 5.8594mA	0x5C = 8.9844mA	0x7C = 12.1094mA
0x1D = 2.8320mA	0x3D = 5.9570mA	0x5D = 9.0820mA	0x7D = 12.2070mA
0x1E = 2.9297mA	0x3E = 6.0547mA	0x5E = 9.1797mA	0x7E = 12.3047mA
0x1F = 3.0273mA	0x3F = 6.1523mA	0x5F = 9.2773mA	0x7F = 12.4024mA
0x80 = 12.5000mA	0xA0 = 15.6250mA	0xC0 = 18.7500mA	0xE0 = 21.8750mA
0x81 = 12.5977mA	0xA1 = 15.7227mA	0xC1 = 18.8477mA	0xE1 = 21.9727mA
0x82 = 12.6953mA	0xA2 = 15.8203mA	0xC2 = 18.9453mA	0xE2 = 22.0703mA
0x83 = 12.7930mA	0xA3 = 15.9180mA	0xC3 = 19.0430mA	0xE3 = 22.1680mA
0x84 = 12.8906mA	0xA4 = 16.0156mA	0xC4 = 19.1406mA	0xE4 = 22.2656mA
0x85 = 12.9883mA	0xA5 = 16.1133mA	0xC5 = 19.2383mA	0xE5 = 22.3633mA
0x86 = 13.0859mA	0xA6 = 16.2109mA	0xC6 = 19.3359mA	0xE6 = 22.4609mA
0x87 = 13.1836mA	0xA7 = 16.3086mA	0xC7 = 19.4336mA	0xE7 = 22.5586mA
0x88 = 13.2813mA	0xA8 = 16.4063mA	0xC8 = 19.5313mA	0xE8 = 22.6563mA
0x89 = 13.3789mA	0xA9 = 16.5039mA	0xC9 = 19.6289mA	0xE9 = 22.7539mA
0x8A = 13.4766mA	0xAA = 16.6016mA	0xCA = 19.7266mA	0xEA = 22.8516mA
0x8B = 13.5742mA	0xAB = 16.6992mA	0xCB = 19.8242mA	0xEB = 22.9492mA
0x8C = 13.6719mA	0xAC = 16.7969mA	0xCC = 19.9219mA	0xEC = 23.0469mA
0x8D = 13.7695mA	0xAD = 16.8945mA	0xCD = 20.0195mA	0xED = 23.1445mA
0x8E = 13.8672mA	0xAE = 16.9922mA	0xCE = 20.1172mA	0xEE = 23.2422mA
0x8F = 13.9649mA	0xAF = 17.0899mA	0xCF = 20.2149mA	0xEF = 23.3399mA
0x90 = 14.0625mA	0xB0 = 17.1875mA	0xD0 = 20.3125mA	0xF0 = 23.4375mA
0x91 = 14.1602mA	0xB1 = 17.2852mA	0xD1 = 20.4102mA	0xF1 = 23.5352mA
0x92 = 14.2578mA	0xB2 = 17.3828mA	0xD2 = 20.5078mA	0xF2 = 23.6328mA
0x93 = 14.3555mA	0xB3 = 17.4805mA	0xD3 = 20.6055mA	0xF3 = 23.7305mA
0x94 = 14.4531mA	0xB4 = 17.5781mA	0xD4 = 20.7031mA	0xF4 = 23.8281mA
0x95 = 14.5508mA	0xB5 = 17.6758mA	0xD5 = 20.8008mA	0xF5 = 23.9258mA
0x96 = 14.6484mA	0xB6 = 17.7734mA	0xD6 = 20.8984mA	0xF6 = 24.0234mA
0x97 = 14.7461mA	0xB7 = 17.8711mA	0xD7 = 20.9961mA	0xF7 = 24.1211mA
0x98 = 14.8438mA	0xB8 = 17.9688mA	0xD8 = 21.0938mA	0xF8 = 24.2188mA
0x99 = 14.9414mA	0xB9 = 18.0664mA	0xD9 = 21.1914mA	0xF9 = 24.3164mA
0x9A = 15.0391mA	0xBA = 18.1641mA	0xDA = 21.2891mA	0xFA = 24.4141mA
0x9B = 15.1367mA	0xBB = 18.2617mA	0xDB = 21.3867mA	0xFB = 24.5117mA
0x9C = 15.2344mA	0xBC = 18.3594mA	0xDC = 21.4844mA	0xFC = 24.6094mA
0x9D = 15.3320mA	0xBD = 18.4570mA	0xDD = 21.5820mA	0xFD = 24.7070mA
0x9E = 15.4297mA	0xBE = 18.5547mA	0xDE = 21.6797mA	0xFE = 24.8047mA
0x9F = 15.5274mA	0xBF = 18.6524mA	0xDF = 21.7774mA	0xFF = 24.9024mA

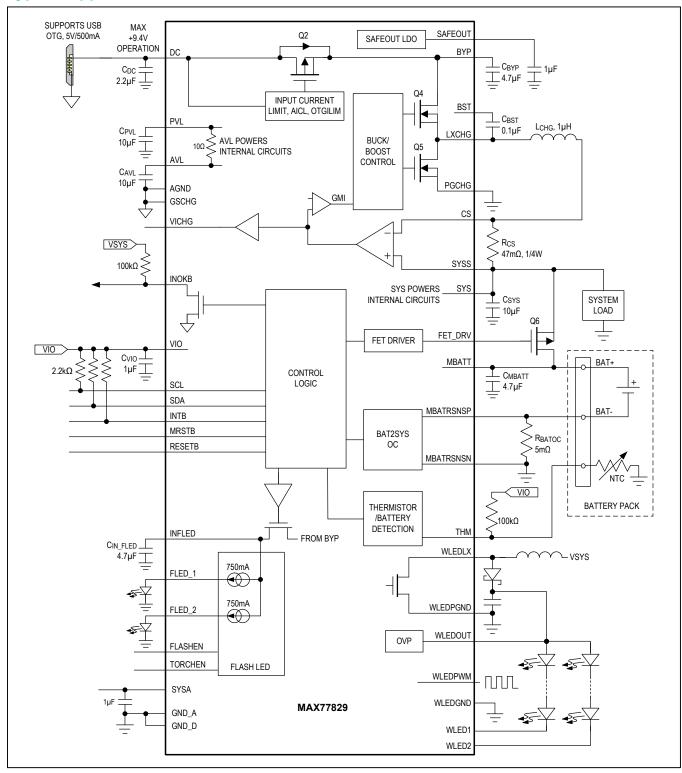
## **WLED Interrupt Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET	
WL	ED_INT	Interrupt Source	0x9B	S1 0x00		
BIT	MODE	NAME	RESET	DESCRIPTION		
3:0	R/C	RESERVED	0000	Reserved		
4	R/C	WLEDOL	0	WLED Converter Current Limit Interrupt 0 = No interrupt pending. 1 = WLED converter has reached the current limit.		
6:5	R/C	RESERVED	00	Reserved		
7	R/C	WLEDOVP	0	WLED Converter has reached the OVP Threshold (Open WLED String) 0 = No interrupt pending. 1 = WLED converter has reached the OVP threshold (open LED string).		

## **WLED Interrupt Mask Register**

N	IAME	FUNCTION	ADDRESS	TYPE	RESET
WLE	D_INT_M	Interrupt Mask	0x9C	S1	0x90
BIT	MODE	NAME	RESET	DESCRIPTION	
3:0	R/W	RESERVED	0000	Reserved	
4	R/W	WLEDOL_M	1	WLED Converter Current Limit Interrupt Mask 0 = Not masked 1 = Masked	
6:5	R/W	RESERVED	00	Reserved	
7	R/W	WLEDOVP_M	1	WLED Converter has reached the OVP Threshold (Open WLED String) Mask 0 = Not masked 1 = Masked	

## **Typical Application Circuit**



## **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX77829EWN+	-40°C to +85°C	56 WLP 0.4mm pitch, 3.64mm x 3.24mm

## **Chip Information**

PROCESS: CMOS

## **Package Information**

For the latest package outline information and land patterns (footprints), go to <a href="www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE	LAND PATTERN
TYPE	CODE	NO.	NO.
56 WLP	W563F3+1	<u>21-1038</u>	Refer to Application Note 1891

#### MAX77829

# Companion PMIC for Smartphone and Tablet

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	12/15	Initial Release	_
1	10/16	Corrected typo; added Register Map and register tables	<b>33, 44</b> –81

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

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